UCC2895x 入力電圧範囲の広いアプリケーションに適した 位相シフト フルブリッジ コントローラ

1 特長

- 拡張ゼロ電圧スイッチング (ZVS) 範囲
- 同期整流器 (SR) の直接制御
- 次のような軽負荷時効率の管理:
  - バースト モード動作
  - 不連続導通モード (DCM)、SR のオン / オフ動的制御
- 勾配補償と電圧モード制御をプログラム可能な、平均またはピーク電流モード制御
- 閉ループのソフトスタートおよびイネーブル機能
- スイッチング周波数を最高 1MHz までプログラム可能、双方向同期あり
- (±3%) サイクルごとの電流制限保護機能、ヒカップ モードをサポート
- 150µA のスタートアップ電流
- V_{DD} 低電圧誤動作防止
- 幅広い温度範囲:-40℃～+125℃

2 アプリケーション

- 位相シフトのフルブリッジ コンバータ
- サーバー用電源
- 産業用電源システム
- 高密度の電源アーキテクチャ

3 概要

UCC28951 コントローラは UCC28950 の拡張版で、UCC28950 と完全に互換性のあるドロップイン代替品です。を参照します。UCC2895x デバイスは、同期整流器 (SR) 出力段の能動制御に加えて、フルブリッジの先進制御を採用しています。

ZVS 動作はさまざまな動作条件で保証されており、負荷電流によって 2 次側同期整流器 (SR) のスイッチング遅延が自動的に調整されるため、システム全体の効率が最大化されます。

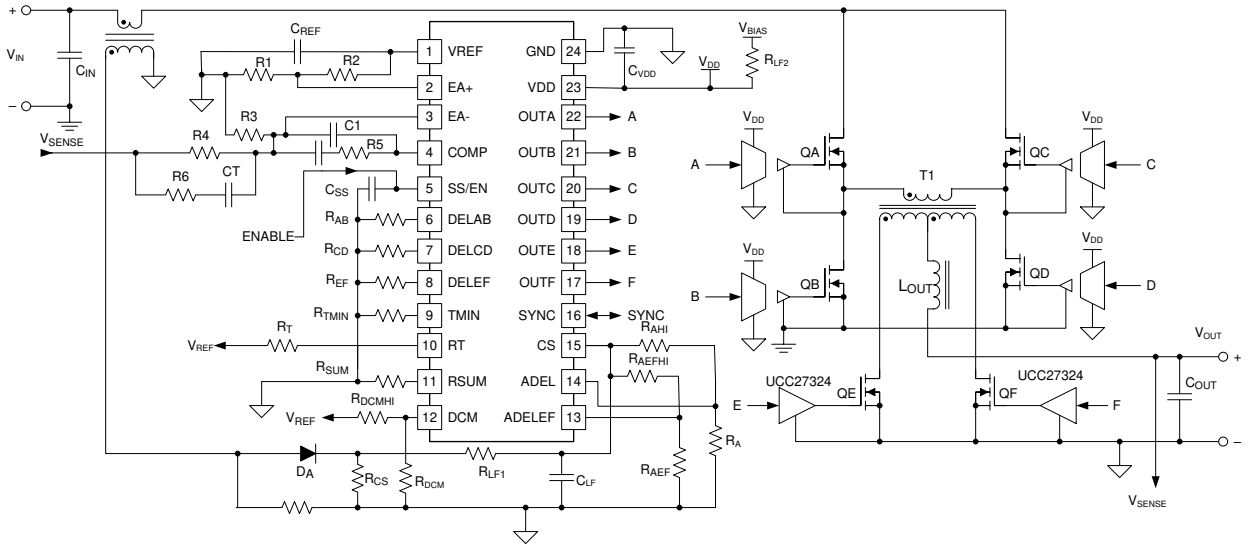
『UCC2895x 600W 位相シフト フルブリッジ設計レビュー / アプリケーション ノート』(SLUA560) を使って、気軽に設計を開始しましょう。

24 ピンの TSSOP パッケージは RoHS に準拠しています。

製品情報

部品番号	パッケージ (1)	本体サイズ (公称)
UCC2895x	TSSOP (24)	7.80mm × 4.40mm

(1) 利用可能なすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。



アプリケーション概略図

このリソースの元の言語は英語です。翻訳は概要を便宜的に提供するもので、自動化ツール (機械翻訳) を使用していることがあり、TI では翻訳の正確性および妥当性につきましては一切保証いたしません。実際の設計などの前には、ti.com で必ず最新の英語版をご参照くださいますようお願いいたします。

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4 Pin Configuration and Functions

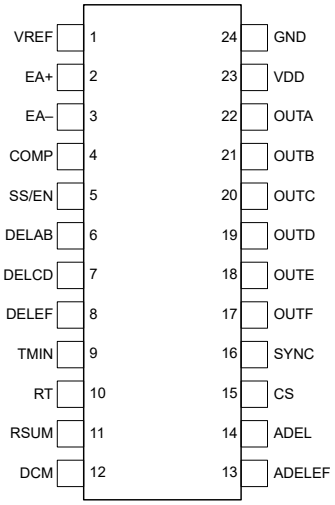

図 4-1. PW Package, 24-Pin TSSOP (Top View)

Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
ADEL	14	I	Dead-time programming for the primary switches over CS voltage range, t_{ABSET} and t_{CDSET}. See セクション 6.3.6
ADELEF	13	I	Delay-time programming between primary side and secondary side switches, t_{AFSET} and t_{BESET}. See セクション 6.3.7
COMP	4	I/O	Error amplifier output and input to the PWM comparator. See セクション 6.3.3
CS	15	I	Current sense for cycle-by-cycle overcurrent protection and adaptive delay functions. See セクション 6.3.14
DCM	12	I	DCM threshold setting. See セクション 6.3.12
DELAB	6	I	Dead-time delay programming between OUTA and OUTB. See セクション 6.3.6
DELCD	7	I	Dead-time delay programming between OUTC and OUTD. See セクション 6.3.6
DELEF	8	I	Delay-time programming between OUTA to OUTF, and OUTB to OUTE. See セクション 6.3.7
EA+	2	I	Error amplifier noninverting input. See セクション 6.3.3
EA–	3	I	Error amplifier inverting input. See セクション 6.3.3
GND	24	—	Ground. All signals are referenced to this node.
OUTA	22	O	0.2A sink and source primary switching output.
OUTB	21	O	
OUTC	20	O	
OUTD	19	O	
OUTE	18	O	
OUTF	17	O	
RSUM	11	I	Slope compensation programming. Voltage mode or peak current mode setting. See セクション 6.3.11
RT	10	I	Oscillator frequency set. leader or follower mode setting. See セクション 6.3.10
SS/EN	5	I	Soft-start programming, device enable and hiccup mode protection circuit. See セクション 6.3.4
SYNC	16	I/O	Synchronization out from leader controller to input of follower controller. See セクション 6.3.15
TMIN	9	I	Minimum duty cycle programming in burst mode. See セクション 6.3.9
VDD	23	I	Bias supply input. See セクション 6.3.17

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Pin Functions (続き)

PIN		TYPE	DESCRIPTION
NAME	NO.		
VREF	1	O	5V, ±1.5%, 20mA reference voltage output. See セクション 6.3.2

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5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1) (2)

	MIN	MAX	UNIT
Input supply voltage, V_{DD} (3)	–0.4	20	V
OUTA, OUTB, OUTC, OUTD, OUTE, OUTF	–0.4	VDD + 0.4	V
Input voltage on DELAB, DELCD, DELEF, SS/EN, DCM, TMIN, RT, SYNC, RSUM, EA+, EA-, COMP, CS, ADEL, ADELEF	–0.4	VREF + 0.4	V
Output voltage on VREF	–0.4	5.6	V
Continuous total power dissipation	See セクション 5.7		
Operating virtual junction temperature, T_J	–40	150	°C
Operating ambient temperature, T_A	–40	125	°C
Lead temperature (soldering, 10 s)		300	°C
Storage temperature, T_{stg}	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under セクション 5.3 is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) These devices are sensitive to electrostatic discharge; follow proper device handling procedures.
(3) All voltages are with respect to GND unless otherwise noted. Currents are positive into, negative out of the specified terminal. See セクション 10 for thermal limitations and considerations of packages.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101(2)	±500	V

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	TYP	MAX	UNIT
Supply voltage, V_{DD}	8	12	17	V
Operating junction temperature	–40		125	°C
Converter switching frequency setting, $F_{SW(nom)}$	50		1000	kHz
Programmable delay between OUTA, OUTB and OUTC, OUTD set by resistors DELAB and DELCD and parameter K_A (1)	30		1000	ns
UCC28950, D_{MAX}			90	%
UCC28951, D_{MAX}			92	%
Programmable delay between OUTA, OUTF and OUTB, OUTE set by resistor DELEF, and parameter K_{EF} (1)	30		1400	ns
Programmable DCM as percentage of voltage at CS(1)	5%		30%	
Programmable T_{MIN}	100		800	ns

(1) Verified during characterization only.

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5.4 Thermal Information

THERMAL METRIC[1]		UCC2895x PW (TSSOP) 24 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	93.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	24.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	47.9	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.7	°C/W
ψ_{JB}	Junction-to-board characterization parameter	47.4	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

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5.5 Electrical Characteristics

V_{DD} = 12V, $T_A = T_J$ = –40°C to +125°C, C_{VDD} = 1µF, C_{REF} = 1µF, R_{AB} = 22.6kΩ, R_{CD} = 22.6kΩ , R_{EF} = 13.3kΩ, R_{SUM} = 124kΩ, R_{TMIN} = 88.7kΩ, R_T = 59kΩ connected between RT pin and 5V voltage supply to set F_{SW} = 100kHz (F_{OSC} = 200kHz) (unless otherwise noted). All component designations are from 図 7-3.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
UNDERVOLTAGE LOCKOUT (UVLO)						
UVLO_RTH	Start threshold		6.75		7.9	V
		T_A = 25°C		7.3		
UVLO_FTH	Minimum operating voltage after start		6.15		7.2	V
		T_A = 25°C		6.7		
UVLO_HYST	Hysteresis		0.53		0.75	V
		T_A = 25°C		0.6		
SUPPLY CURRENTS						
$I_{DD(off)}$	Startup current	V_{DD} = 5.2V			270	µA
		V_{DD} = 5.2V, T_A = 25°C		150		
I_{DD}	Operating supply current				10	mA
		T_A = 25°C		5		
VREF OUTPUT VOLTAGE						
V_{REF}	VREF total output range	0 ≤ I_R ≤ 20mA, 8V ≤ V_{DD} ≤ 17V	4.925		5.075	V
		0 ≤ I_R ≤ 20mA, 8V ≤ V_{DD} ≤ 17V, T_A = 25°C		5		
I_{SCC}	Short circuit current	V_{REF} = 0V	–53		–23	mA
SWITCHING FREQUENCY (½ OF INTERNAL OSCILLATOR FREQUENCY F_{OSC})						
$F_{SW(nom)}$	Total range		92		108	kHz
		T_A = 25°C		100		
D_{MAX}	Maximum duty cycle				97%	
		T_A = 25°C		95%		
SYNCHRONIZATION						
PH_{SYNC}	Total range	R_T = 59kΩ between RT and GND, Input pulses 200kHz, D = 0.5 at SYNC	85		95	°PH
		R_T = 59kΩ between RT and GND, Input pulses 200kHz, D = 0.5 at SYNC, T_A = 25°C		90		
F_{SYNC}	Total range	R_T = 59kΩ between RT and 5V; –40 °C ≤ T_J ≤ 125°C	180		220	kHz
		T_A = 25°C		200		
T_{PW}	Pulse width		2.2		2.8	µs
		T_A = 25°C		2.5		

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V_{DD} = 12V, T_A = T_J = –40°C to +125°C, C_{VDD} = 1µF, C_{REF} = 1µF, R_{AB} = 22.6kΩ, R_{CD} = 22.6kΩ , R_{EF} = 13.3kΩ, R_{SUM} = 124kΩ, R_{TMIN} = 88.7kΩ, R_T = 59kΩ connected between RT pin and 5V voltage supply to set F_{SW} = 100kHz (F_{OSC} = 200kHz) (unless otherwise noted). All component designations are from 図 7-3.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
ERROR AMPLIFIER						
V_{ICM}	Common-mode input voltage range	V_{ICM} range ensures parameters, the functionality ensured for 3.6V < V_{ICM} < VREF + 0.4V, and –0.4V < V_{ICM} < 0.5V	0.5		3.6	V
V_{IO}	Offset voltage		– 7		7	mV
I_{BIAS}	Input bias current		–1		1	µA
EA_{HIGH}	High-level output voltage	$V_{(EA+)}$ – $V_{(EA–)}$ = 500mV, I_{EAOUT} = –0.5mA	3.9			V
		$V_{(EA+)}$ – $V_{(EA–)}$ = 500mV, I_{EAOUT} = –0.5mA, T_A = 25°C		4.25		
EA_{LOW}	Low-level output voltage	$V_{(EA+)}$ – $V_{(EA–)}$ = –500mV, I_{EAOUT} = 0.5mA			0.35	V
		$V_{(EA+)}$ – $V_{(EA–)}$ = –500mV, I_{EAOUT} = 0.5mA, T_A = 25°C		0.25		
I_{SOURCE}	Error amplifier source current		–8		–0.5	mA
		T_A = 25°C		–3.75		
I_{SINK}	Error amplifier sink current		2.7		5.75	mA
		T_A = 25°C		4.6		
I_{VOL}	Open-loop DC gain	T_A = 25°C		100		dB
GBW	Unity gain bandwidth(1)	T_A = 25°C		3		MHz
CYCLE-BY-CYCLE CURRENT LIMIT						
V_{CS_LIM}	CS pin cycle-by-cycle threshold		1.94		2.06	V
		T_A = 25°C		2		
INTERNAL HICCUP MODE SETTINGS						
I_{DS}	Discharge current to set cycle-by-cycle current limit duration	V_{CS} = 2.5V, V_{VSS} = 4V	15		25	µA
		V_{CS} = 2.5V, V_{VSS} = 4V, T_A = 25°C		20		
V_{HCC}	Hiccup OFF time threshold		3.2		4.2	V
		T_A = 25°C		3.6		
I_{HCC}	Discharge current to set Hiccup Mode OFF Time		1.9		3.2	µA
		T_A = 25°C		2.55		
SOFT START/ENABLE						
I_{SS}	Charge current	V_{SS} = 0V	20		30	µA
		T_A = 25°C		25		
V_{SS_STD}	Shutdown, restart threshold		0.25		0.7	V
		T_A = 25°C		0.5		
V_{SS_PU}	Pullup threshold		3.3		4.3	V
		T_A = 25°C		3.7		
V_{SS_CL}	Clamp voltage		4.2		4.95	V
		T_A = 25°C		4.65		

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V_{DD} = 12V, T_A = T_J = –40°C to +125°C, C_{VDD} = 1µF, C_{REF} = 1µF, R_{AB} = 22.6kΩ, R_{CD} = 22.6kΩ , R_{EF} = 13.3kΩ, R_{SUM} = 124kΩ, R_{TMIN} = 88.7kΩ, R_T = 59kΩ connected between RT pin and 5V voltage supply to set F_{SW} = 100kHz (F_{OSC} = 200kHz) (unless otherwise noted). All component designations are from 図 7-3.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
LIGHT-LOAD EFFICIENCY CIRCUIT						
V_{DCM}	DCM threshold	V_{DCM} = 0.4V, Sweep CS confirm there are OUTE and OUTF pulses, T_A = 25°C	0.37	0.39	0.41	V
		V_{DCM} = 0.4V, Sweep CS, confirm there are OUTE and OUTF pulses, 0°C ≤ T_A ≤ 85°CDCM threshold, (6)	0.364	0.39	0.416	V
		V_{DCM} = 0.4V, Sweep CS, confirm there are OUTE and OUTF pulses, –40°C ≤ T_A ≤ 125°C(6)	0.35	0.39	0.43	V
I_{DCM_SRC}	DCM Sourcing Current	CS < DCM threshold	14		26	µA
		CS < DCM threshold, T_A = 25°C		20		
OUTPUTS OUTA, OUTB, OUTC, OUTD, OUTE, OUTF						
$I_{SINK/SRC}$	Sink and source peak current(6)	T_A = 25°C		0.2		A
R_{SRC}	Output source resistance	I_{OUT} = 20mA	10		35	Ω
		I_{OUT} = 20mA, T_A = 25°C		20		
R_{SINK}	Output sink resistance	I_{OUT} = 20mA	5		30	Ω
		I_{OUT} = 20mA, T_A = 25°C		10		
THERMAL SHUTDOWN						
	Rising threshold(6)	T_A = 25°C		160		°C
	Falling threshold(6)	T_A = 25°C		140		°C
	Hysteresis			20		°C

(1) See 図 6-1 for timing diagram and T_{ABSET1}, T_{ABSET2}, T_{CDSET1}, T_{CDSET2} definitions.
(2) See 図 6-4 for timing diagram and T_{AFSET1}, T_{AFSET2}, T_{BESET1}, T_{BESET2} definitions.
(3) Pair of outputs OUTC, OUTE and OUTD, OUTF always going high simultaneously.
(4) Outputs A or B are never allowed to go high if both outputs OUTE and OUTF are high.
(5) All delay settings are measured relative to 50% of pulse amplitude.
(6) Verified during characterization only.

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5.6 Timing Requirements

		MIN	NOM	MAX	UNIT
CYCLE-BY-CYCLE CURRENT LIMIT					
T_{CS}	Propagation delay from CS to OUTC and OUTD outputs Input pulse between CS and GND from zero to 2.5 V		100		ns
PROGRAMMABLE DELAY TIME SET ACCURACY AND RANGE(1) (2) (3) (4) (5)					
T_{ABSET1}	Short delay time set accuracy between OUTA and OUTB CS = ADEL = ADELEF = 1.8 V	32	45	56	ns
T_{ABSET2}	Long delay time set accuracy between OUTA and OUTB CS = ADEL = ADELEF = 0.2 V	216	270	325	ns
T_{CDSET1}	Short delay time set accuracy between OUTC and OUTD CS = ADEL = ADELEF = 1.8 V	32	45	56	ns
T_{CDSET2}	Long delay time set accuracy between OUTC and OUTD CS = ADEL = ADELEF = 0.2 V	216	270	325	ns
T_{AFSET1}	Short delay time set accuracy between falling OUTA, OUTF CS = ADEL = ADELEF = 0.2 V	22	35	48	ns
T_{AFSET2}	Long delay time set accuracy between falling OUTA, OUTF CS = ADEL = ADELEF = 1.8 V	190	240	290	ns
T_{BESET1}	Short delay time set accuracy between falling OUTB, OUTE CS = ADEL = ADELEF = 0.2 V	22	35	48	ns
T_{BESET2}	Long delay time set accuracy between falling OUTB, OUTE CS = ADEL = ADELEF = 1.8 V	190	240	290	ns
ΔT_{ADBC}	Pulse matching between OUTA rise, OUTD fall and OUTB rise, OUTC fall CS = ADEL = ADELEF = 1.8 V, COMP = 2 V	–50	0	50	ns
ΔT_{ABBA}	Half cycle matching between OUTA rise, OUTB rise and OUTB rise, OUTA rise CS = ADEL = ADELEF = 1.8 V, COMP = 2 V	–50	0	50	ns
ΔT_{EEFF}	Pulse matching between OUTE fall, OUTE rise and OUTF fall, OUTF rise CS = ADEL = ADELEF = 0.2 V, COMP = 2 V	–60	0	60	ns
ΔT_{EFFE}	Pulse matching between OUTE fall, OUTF rise and OUTF fall, OUTE rise CS = ADEL = ADELEF = 0.2 V, COMP = 2 V	–60	0	60	ns
LIGHT-LOAD EFFICIENCY CIRCUIT					
T_{MIN}	Total range, R_{TMIN} = 88.7 kΩ	425	525	625	ns
OUTPUTS OUTA, OUTB, OUTC, OUTD, OUTE, OUTF					
T_R	Rise time, C_{LOAD} = 100 pF		9	25	ns
T_F	Fall time, C_{LOAD} = 100 pF		7	25	ns

5.7 Dissipation Ratings

over operating free-air temperature range (unless otherwise noted)

PACKAGE	DERATING FACTOR	POWER RATING		
	ABOVE T_A = 25°C	T_A < 25°C	T_A = 70°C	T_A = 85°C
PW	10.7mW/°C	1.07W	0.59W	0.429W

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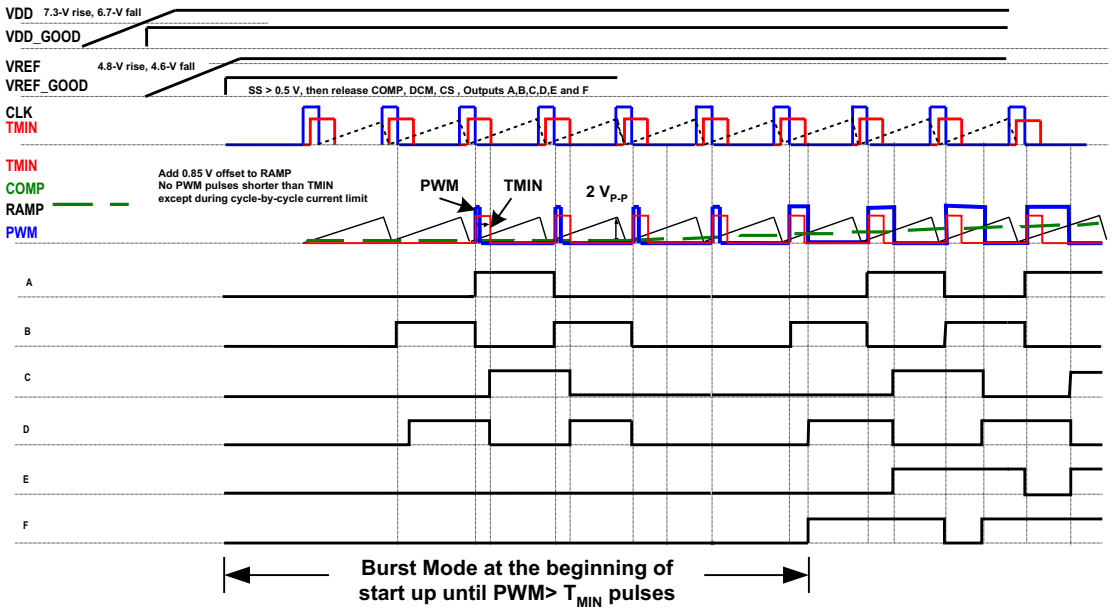
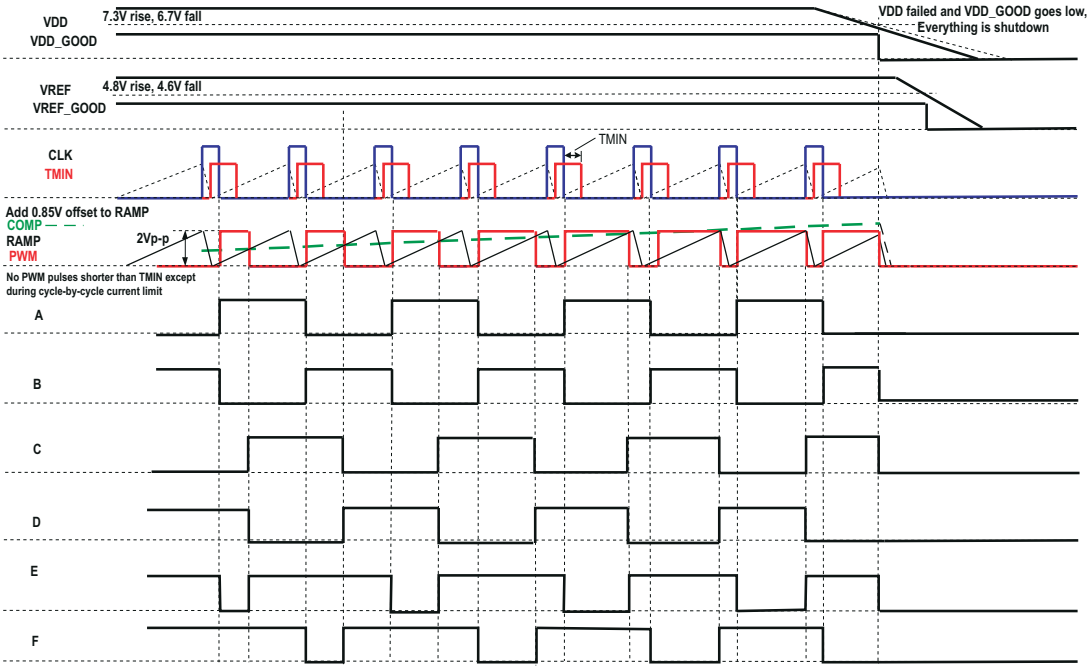


No output delay shown, COMP-to-RAMP offset not included.

There is no pulse on OUTE during burst mode at start-up. Two falling edge PWM pulses are required before enabling the synchronous rectifier outputs. Narrower pulse widths (less than 50% duty cycle) may be observed in the 1st OUTD pulse of a burst. The user must design the bootstrap capacitor charging circuit of the gate driver device so that the first OUTC pulse is transmitted to the MOSFET gate in all cases. Transformer based gate driver circuits are not affected. This behavior is described in more detail in the *Gate Drive Outputs on the UCC28950 and UCC2895x During Burst Mode Operation* (SLAU787) application note.

図 5-1. UCC2895x Start-Up Timing



No output delay shown, COMP-to-RAMP offset not included.

図 5-2. UCC2895x Steady-State and Shutdown Timing Diagram

5.8 Typical Characteristics

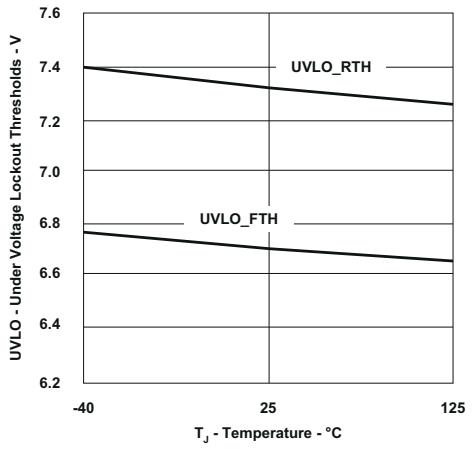


図 5-3. UVLO Thresholds vs Temperature

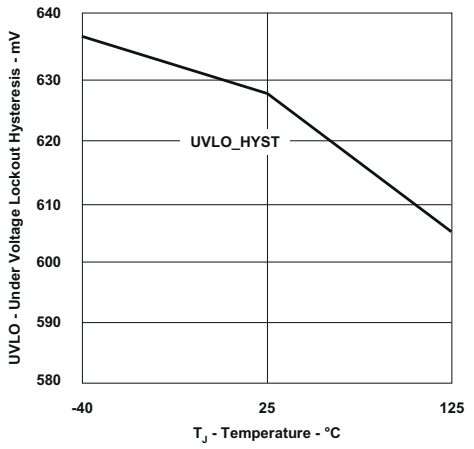


図 5-4. UVLO Hysteresis vs Temperature

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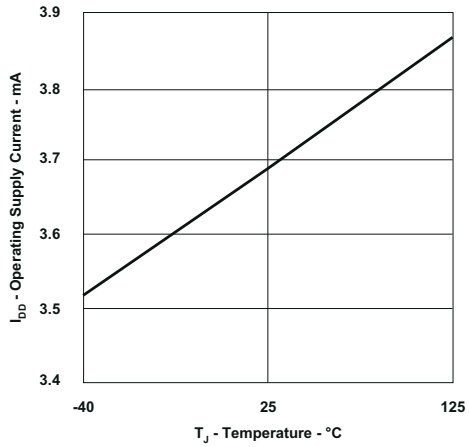

図 5-5. Supply Current vs Temperature

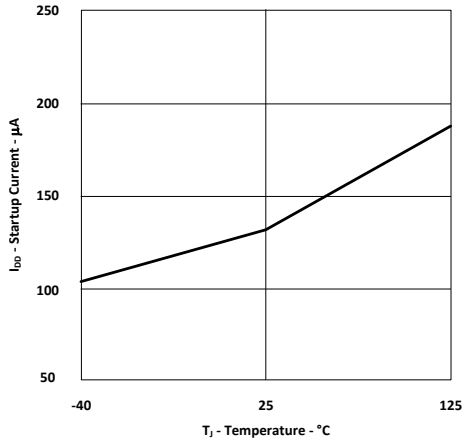

図 5-6. Start-Up Current vs Temperature

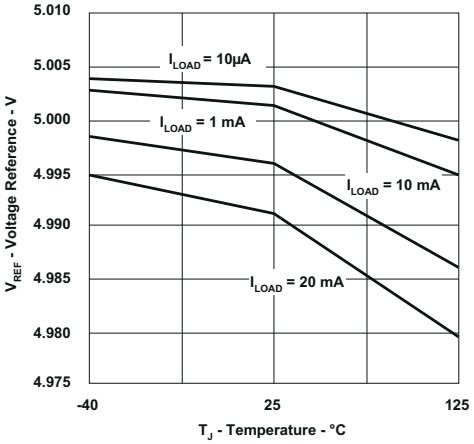

図 5-7. Voltage Reference (VDD = 12V) vs Temperature

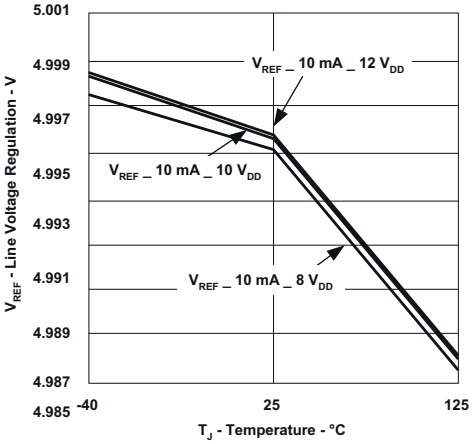

図 5-8. Line Voltage Regulation (I_{LOAD} = 10mA) vs Temperature

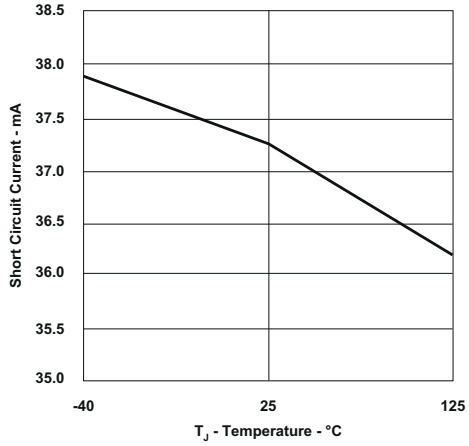

図 5-9. Short-Circuit Current vs Temperature

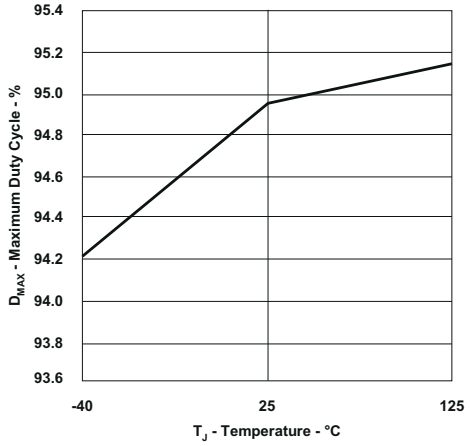

図 5-10. Maximum Duty Cycle vs Temperature

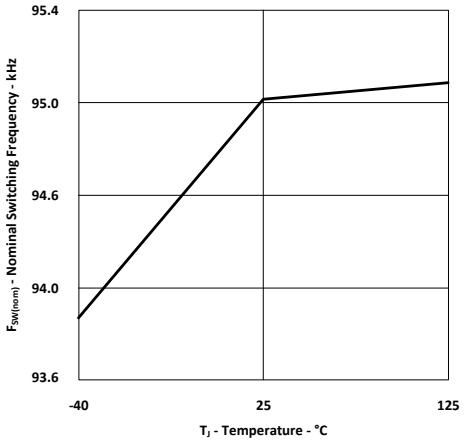

図 5-11. Nominal Switching Frequency vs Temperature

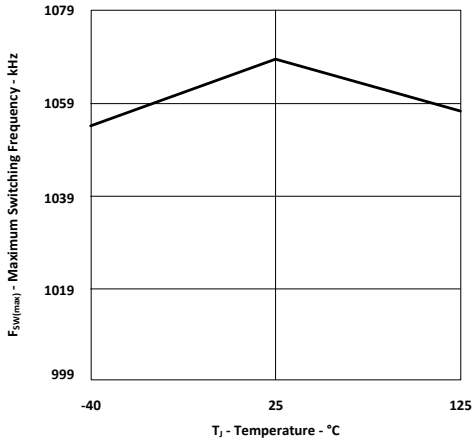

図 5-12. Maximum Switching Frequency vs Temperature

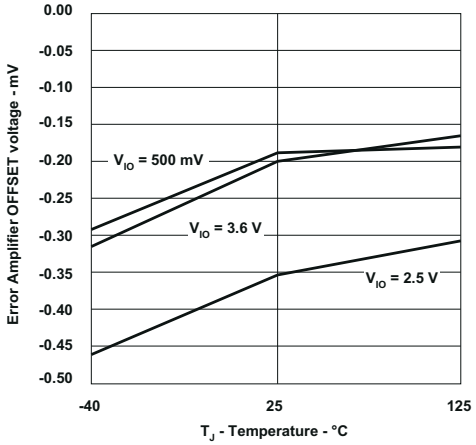

図 5-13. Error Amplifier Offset Voltage vs Temperature

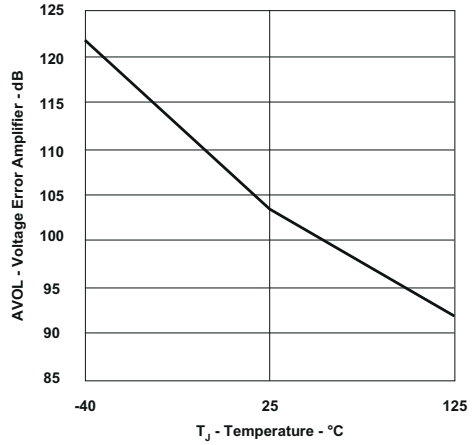

図 5-14. Voltage Error Amplifier (Open-Loop Gain) vs Temperature

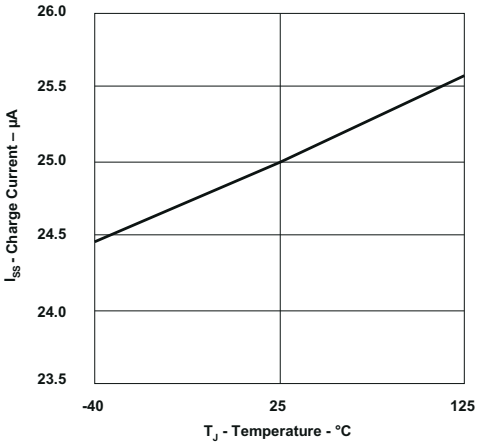

図 5-15. I_{SS} Charge Current vs Temperature

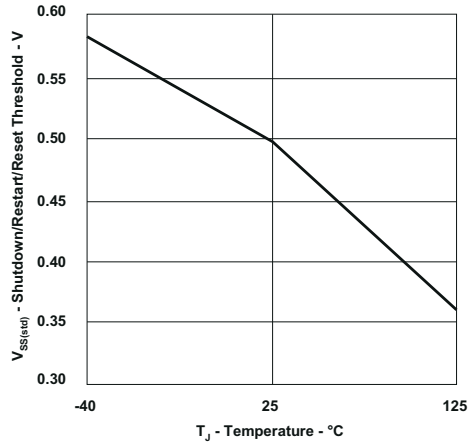

図 5-16. Shutdown, Restart, and Reset Threshold vs Temperature

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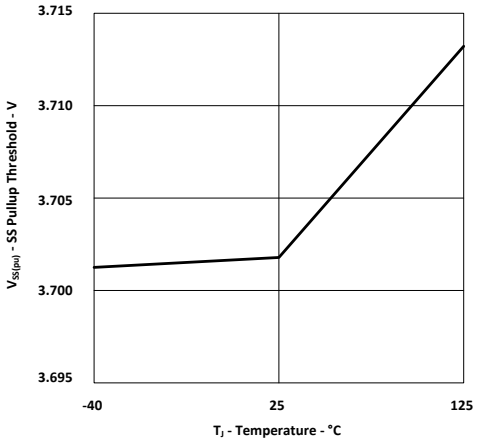

図 5-17. SS Pullup Threshold vs Temperature

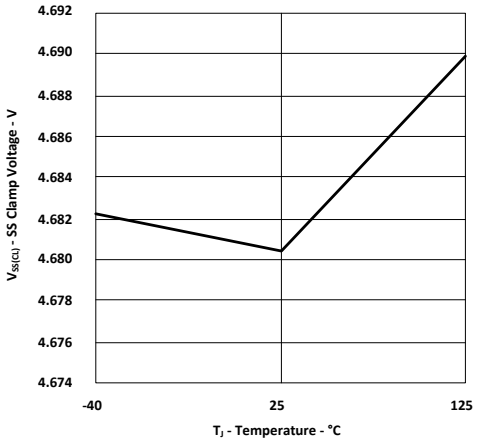

図 5-18. SS Clamp Voltage vs Temperature

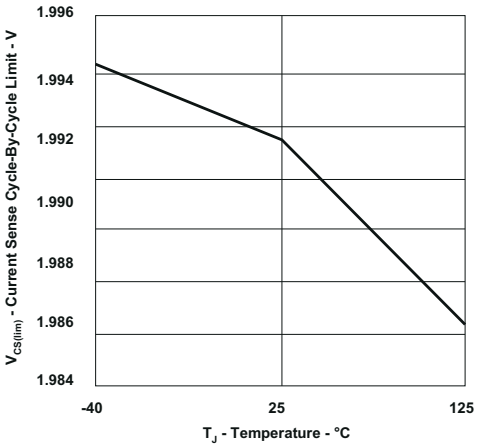

図 5-19. Current Sense Cycle-by-Cycle Limit vs Temperature

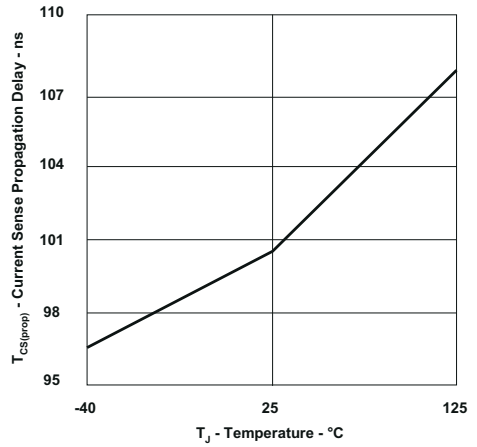

図 5-20. Current Sense Propagation Delay vs Temperature

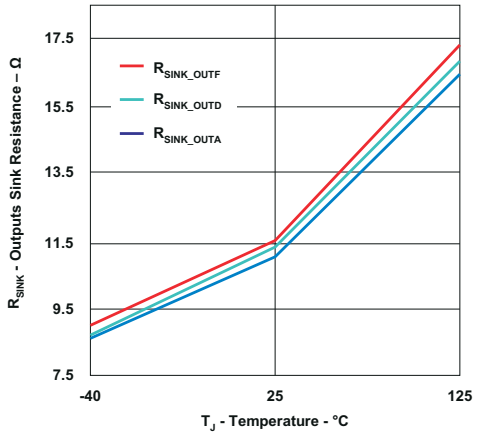

図 5-21. Outputs Sink Resistance vs Temperature

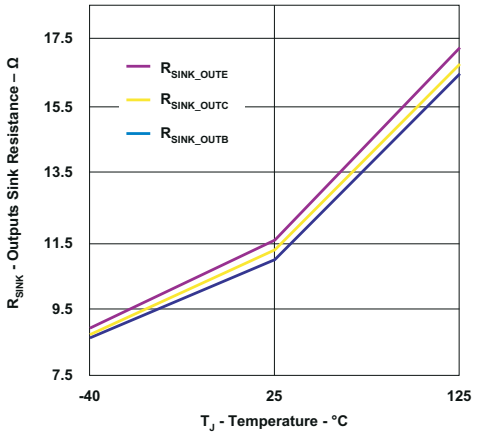

図 5-22. Outputs Sink Resistance vs Temperature

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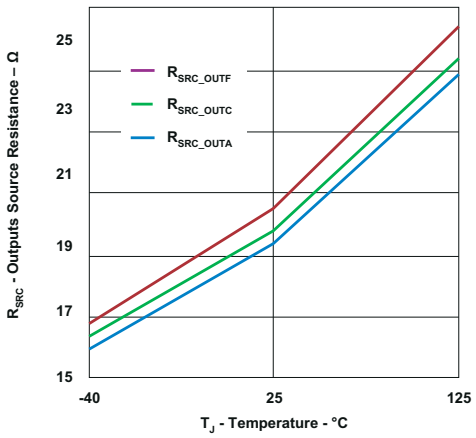

図 5-23. Outputs Source Resistance vs Temperature

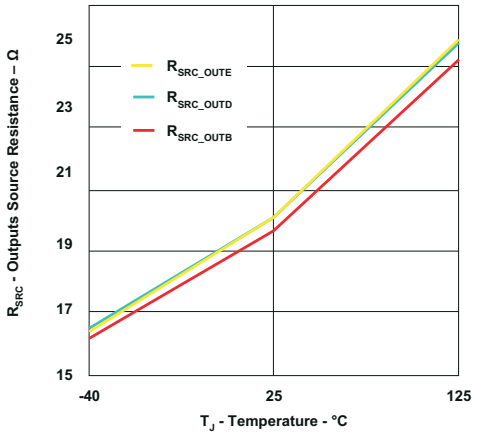

図 5-24. Outputs Source Resistance vs Temperature

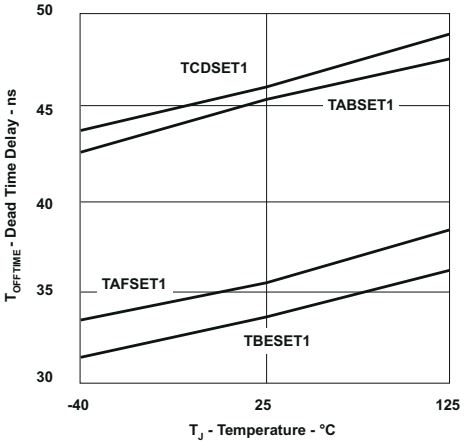

図 5-25. Dead Time Delay vs Temperature

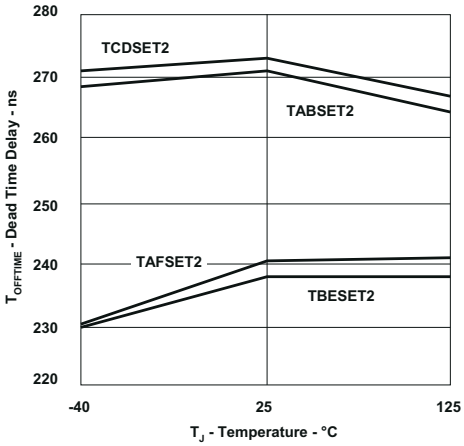

図 5-26. Dead Time Delay vs Temperature

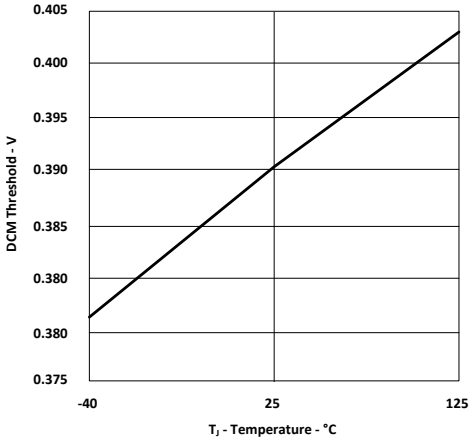

図 5-27. DCM Threshold vs Temperature

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6 Detailed Description

6.1 Overview

The UCC2895x controllers combine all the functions necessary to control a phase-shifted, full-bridge, power stage in a 24-pin TSSOP package. The controller includes two synchronous-rectifier (SR), gate-drive outputs as well as the outputs needed to drive all four switches in the full-bridge circuit. The dead times between the upper and lower switches in the full bridge may be set using the DELAB and DELCD inputs. Further, this dead time may be dynamically adjusted according to the load level using the ADEL pin. This adjustment allows the user to optimize the dead time for their particular power circuit and to achieve ZVS over the entire operating range. In a similar manner, the dead times between the full-bridge switches and the secondary SRs may be optimized using the DELEF input. This dead time may also be dynamically adjusted according to the load, using the ADELEF input to the controller. A DCM (discontinuous conduction mode) option disables the SRs at a user settable light load to improve power circuit efficiency. The controller enters a light-load-burst mode if the feedback loop demands a conduction time less than a user settable level (TMIN).

At higher-power levels, two or more UCC2895x controllers may be easily synchronized in a leader/follower configuration. A SS/EN input may be used to set the length of the soft start process and to turn the controller on and off. The controller may be configured for voltage mode or current mode control. Cycle-by-cycle current limiting is provided in voltage mode and peak current mode. Users can set the switching frequency over a wide range making this controller suited to both IGBT and MOSFET based designs.

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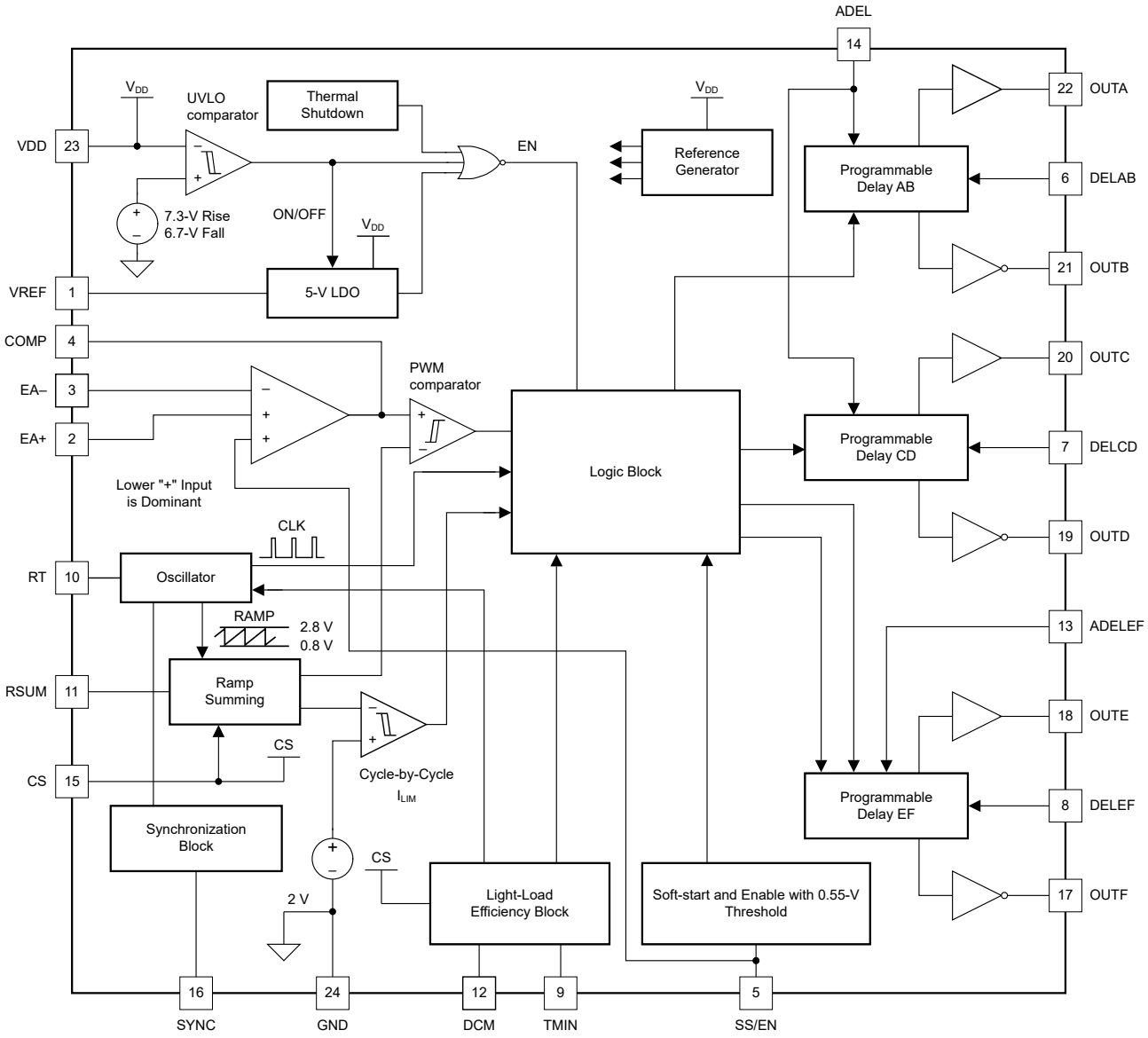
6.2 Functional Block Diagram



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6.3 Feature Description

6.3.1 Start-Up Protection Logic

Before the UCC2895x controllers will start up, the following conditions must be met:

- VDD voltage exceeds rising UVLO threshold 7.3V typical.
- The 5V reference voltage is available.
- Junction temperature is below the thermal shutdown threshold of 140°C.
- The voltage on the soft-start capacitor is not below 0.55V typical.

If all those conditions are met, an internal enable signal EN is generated that initiates the soft-start process. The duty cycle during the soft start is defined by the voltage at the SS pin, and cannot be lower than the duty cycle set by TMIN, or by cycle-by-cycle current limit circuit depending on load conditions.

6.3.2 Voltage Reference (VREF)

The accurate (±1.5%) 5V reference voltage regulator with a short-circuit protection circuit supplies internal circuitry and provides up to 20mA external output current. Place a low ESR and ESL, preferably ceramic decoupling capacitor C_{REF} in 1µF to 2.2µF range from this pin to GND as close to the related pins as possible for best performance. The only condition where the reference regulator is shut down internally is during undervoltage lockout.

6.3.3 Error Amplifier (EA+, EA–, COMP)

The error amplifier has two uncommitted inputs, EA+ and EA–, with a 3MHz unity gain bandwidth, which allows flexibility in closing the feedback loop. The EA+ is a noninverting input, the EA– is an inverting input and the COMP is the output of the error amplifier. The input voltage common-mode range, where the parameters of the error amplifier are ensured, is from 0.5V to 3.6V. The output of the error amplifier is connected internally to the noninverting input of the PWM comparator. The range of the error amplifier output of 0.25V to 4.25V far exceeds the PWM comparator input ramp-signal range, which is from 0.8V to 2.8V. The soft-start signal serves as an additional noninverting input of the error amplifier. The lower of the two noninverting inputs of the error amplifier is the dominant input and sets the duty cycle where the output signal of the error amplifier is compared with the internal ramp at the inputs of the PWM comparator.

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6.3.4 Soft-Start and Enable (SS/EN)

The soft-start pin (SS/EN) is a multi-function pin used for the following operations:

- Closed-loop soft start with the gradual duty cycle increase from the minimum set by TMIN up to the steady-state duty cycle required by the regulated output voltage.
- Setting hiccup mode conditions during cycle-by-cycle overcurrent limit.
- On/off control for the converter.

During the soft-start sequence, one of the voltages at the SS/EN or EA+ pins, whichever is lower (SS/EN – 0.55 V) or EA+ voltage (see セクション 6.2), sets the reference voltage for a closed feedback loop. Both SS/EN and EA+ signals are noninverting inputs of the error amplifier with the COMP pin being its output. Thus the soft-start time always goes under the closed feedback loop and the voltage at COMP pin sets the duty cycle. The duty cycle defined by the COMP pin voltage can not be shorter than TMIN pulse width set by the user. However, if the shortest duty cycle is set by the cycle-by-cycle current limit circuit, then it becomes dominant over the duty cycle defined by the COMP pin voltage or by the TMIN block.

The soft-start duration is defined by an external capacitor C_{SS}, connected between the SS/EN pin and ground, and the internal charge current that has a typical value of 25 µA. Pulling the soft-start pin externally below 0.55 V shuts down the controller. The release of the soft-start pin enables the controller to start, and if there is no current limit condition, the duty cycle applied to the output inductor gradually increases until it reaches the steady-state duty cycle defined by the regulated output voltage of the converter. This increase happens when the voltage at the SS/EN pin reaches and then exceeds by 0.55 V, the voltage at the EA+ pin. Thus for the given soft-start time T_{SS}, the C_{SS} value can be defined by 式 1 or 式 2:

$$C_{SS(leader)} = \frac{T_{SS} \times 25\ \mu A}{\left(0.55 + V_{(EA+)}\right)} \quad (1)$$

$$C_{SS(follower)} = \frac{T_{SS} \times 25\ \mu A}{825\ k\Omega \times \ln\left(\frac{20.6}{20.6 - 0.55 - V_{(EA+)}}\right)} \quad (2)$$

For example, in 式 1, if the soft-start time T_{SS} is 10 ms, and the EA+ pin is 2.5 V, then the soft-start capacitor C_{SS} is equal to 82 nF.

注

If the converter is configured to operate in follower mode, connect a 825-kΩ (±5%) resistor from the SS pin to ground.

6.3.5 Light-Load Power Saving Features

The UCC2895x offers four different light-load management techniques for improving the efficiency of a power converter over a wide load current range.

1. Adaptive Delay,
   a. ADEL, which sets and optimizes the dead-time control for the primary switches over a wide load current range.
   b. ADELEF, which sets and optimizes the delay-time control between the primary side switches and the secondary side switches.
2. TMIN, sets the minimum pulse width as long as the part is not in current limit mode.
3. Dynamic synchronous rectifier on/off control in DCM Mode, For increased efficiency at light loads. The DCM Mode starts when the voltage at CS pin is lower than the threshold set by the user. In DCM Mode, the synchronous output drive signals OUTE and OUTF are brought down low.
4. Burst Mode, for maximum efficiency at very light loads or no load. Burst Mode has an even number of PWM TMIN pulses followed by off time. Transition to the Burst Mode is defined by the TMIN duration set by the user.

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6.3.6 Adaptive Delay, (Delay Between OUTA and OUTB, OUTC and OUTD (DELAB, DELCD, ADEL))

The resistor R_{AB} from the DELAB pin, DELAB to GND, along with the resistor divider R_{AHI} from CS pin to ADEL pin and R_A from ADEL pin to GND sets the delay T_{ABSET} between one of outputs OUTA or OUTB going low and the other output going high 図 6-1. The total resistance of this resistor divider should be in the range between 10kΩ and 20kΩ

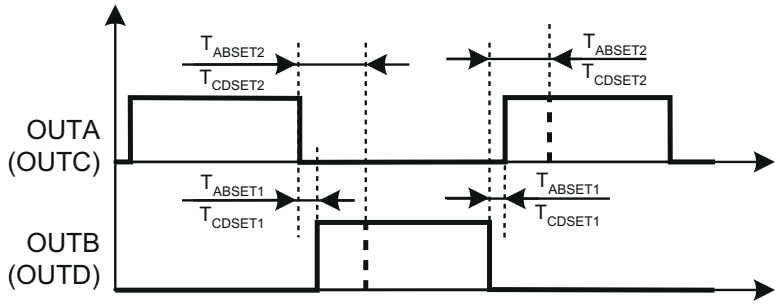

図 6-1. Delay Definitions Between OUTA and OUTB, OUTC and OUTD

This delay gradually increases as a function of the CS signal from T_{ABSET1}, which is measured at V_{CS} = 1.8V, to T_{ABSET2}, which is measured at the V_{CS} = 0.2V. This approach ensures there will be no shoot-through current during the high-side and low-side MOSFET switching and optimizes the delay for acheiving ZVS condition over a wide load current range. The ratio between the longest and shortest delays is set by the resistor divider R_{AHI} and R_A. The maximum ratio is achieved by tying the CS and ADEL pins together. If ADEL is connected to GND, then the delay is fixed, defined only by the resistor R_{AB} from DELAB to GND. The delay T_{CDSET1} and T_{CDSET2} settings and their behaviour for outputs OUTC and OUTD are very similar to the one described for OUTA and OUTB. The difference is that resistor R_{CD} connected between DELCD pin and GND sets the delay T_{CDSET}. The ratio between the longest and shortest delays is set by the resistor divider R_{AHI} and R_A.

The delay time T_{ABSET} is defined by the following 式 3 .

$$T_{ABSET} = \frac{R_{AB} \times 5V}{CS \times K_A \times 0.927 + 0.22V} \times 1pF - 12.6ns \quad (3)$$

where

- the CS, which is the voltage at pin CS, is in volts
- K_A is a numerical gain factor of CS voltage from 0 to 1

The same equation is used to define the delay time T_{CDSET} in another leg, except R_{AB} is replaced by R_{CD} (see 式 4).

$$T_{CDSET} = \frac{R_{CD} \times 5V}{CS \times K_A \times 0.927 + 0.22V} \times 1pF - 12.6ns \quad (4)$$

where

- the CS, which is the voltage at pin CS, is in volts
- K_A is a numerical gain factor of CS voltage from 0 to 1

These equations are empirical and they are approximated from measured data. Thus, there is no unit agreement in the equations. As an example, assume R_{AB} = 15kΩ, CS = 1V and K_A = 0.5. Then the T_{ABSET} is approximately 90ns.

In 式 5, K_A is the same and is defined as 式 5:

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$$K_A = \frac{R_A}{R_A + R_{AHI}} \quad (5)$$

K_A sets how the delay varies with the CS pin voltage as shown in 図 6-2 and 図 6-3.

TI recommends starting by setting K_A = 0 and set T_{ABSET} and T_{CDSET} relatively large using equations or plots in this data sheet to avoid hard switching or even shoot through current. The delay between outputs A, B and C, D set by resistors R_{AB} and R_{CD} accordingly. Program the optimal delays at light load first. Then by changing K_A set the optimal delay for the outputs A, B at maximum current. K_A for outputs C, D is the same as for A, B. Usually outputs C, D always have ZVS if sufficient delay is provided.

注

The allowed resistor range on DELAB and DELCD, R_{AB} and R_{CD} is 13kΩ to 90kΩ.

R_A and R_{AHI} define the portion of voltage at pin CS applied to the pin ADEL (see 図 7-3). K_A defines how significantly the delay time depends on CS voltage. K_A varies from 0, where ADEL pin is shorted to ground (R_A = 0) and the delay does not depend on CS voltage, to 1, where ADEL is tied to CS (R_{AHI} = 0). Setting K_A, R_{AB}, and R_{CD} provides the ability to maintain optimal ZVS conditions of primary switches over load current because the voltage at CS pin includes the load current reflected to the primary side through the current-sensing circuit. The plots in 図 6-2 and 図 6-3 show the delay time settings as a function of CS voltage and K_A for two different conditions: R_{AB} = R_{CD} = 13kΩ (図 6-2) and R_{AB} = R_{CD} = 90kΩ (図 6-3).

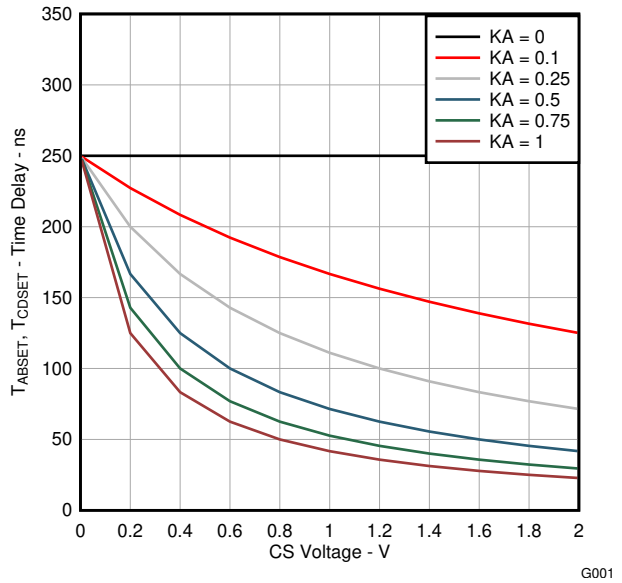

図 6-2. Delay Time Set T_{ABSET} and T_{CDSET} (Over CS Voltage Variation and selected K_A for R_{AB} and R_{CD} Equal 13kΩ)

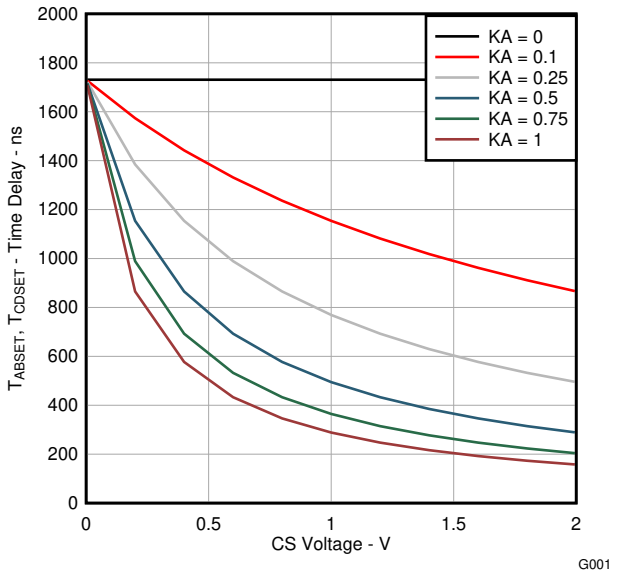

図 6-3. Delay Time set T_{ABSET} and T_{CDSET} (Over CS Voltage Variation and Selected K_A for R_{AB} and R_{CD} Equal 90 kΩ)

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6.3.7 Adaptive Delay (Delay Between OUTA and OUTF, OUTB and OUTE (DELEF, ADELEF)

The resistor R_{EF} from the DELEF pin to GND along with the resistor divider R_{AEFHI} from CS pin to ADELEF pin and R_{AEF} from ADELEF pin to GND sets equal delays T_{AFSET} and T_{BESET} between outputs OUTA or OUTB going low and related output OUTF or OUTE going low 図 6-4. The total resistance of this resistor divider should be in the range between 10kΩ and 20kΩ.

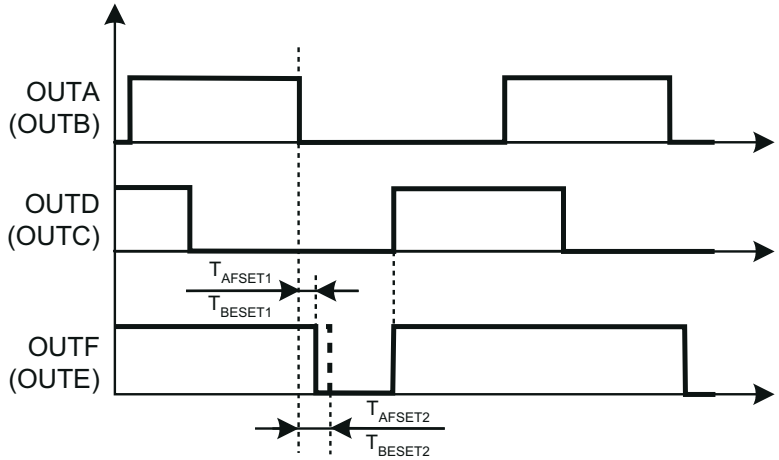

図 6-4. Delay Definitions Between OUTA and OUTF, OUTB and OUTE

These delays gradually increase as function of the CS signal from T_{AFSET1}, which is measured at V_{CS} = 0.2V, to T_{AFSET2}, which is measured at V_{CS} = 1.8V. This is opposite to the DELAB and DELCD behavior and this delay is longest (T_{AFSET2}) when the signal at CS pin is maximized and shortest (T_{AFSET1}) when the CS signal is minimized. This approach will reduce the synchronous rectifier MOSFET body diode conduction time over a wide load current range thus improving efficiency. The ratio between the longest and shortest delays is set by the resistor divider R_{AEFHI} and R_{AEF}. If CS and ADELEF are tied, the ratio is maximized. If ADELEF is connected to GND, then the delay is fixed, defined only by resistor R_{EF} from DELEF to GND.

The delay time T_{AFSET} is defined by the following 式 6. 式 6 also defines the delay time T_{BESET}.

$$T_{AFSET} = T_{BESET} = \frac{R_{EF} \times 5V}{-CS \times K_{EF} \times 0.993 + 2.063V} \times 1pF - 1.3ns \quad (6)$$

where

- the CS, which is the voltage at pin CS, is in volts
- K_{EF} is a numerical gain factor of CS voltage from 0 to 1

式 7 is an empirical approximation of measured data, thus, there is no unit agreement in it. As an example, assume R_{EF} = 15kΩ, CS = 1V and K_{EF} = 0.5. Then the T_{AFSET} is going to be 41.7ns. K_{EF} is defined as 式 7:

$$K_{EF} = \frac{R_{AEF}}{R_{AEF} + R_{AEF(hi)}} \quad (7)$$

R_{AEF} and R_{AEFHI} define the portion of voltage at pin CS applied to the pin ADELEF (see 図 7-3). K_{EF} defines how significantly the delay time depends on CS voltage. K_{EF} varies from 0, where ADELEF pin is shorted to ground (R_{AEF} = 0) and the delay does not depend on CS voltage, to 1, where ADELEF is tied to CS (R_{AEFHI} = 0).

注

The allowed resistor range on DELEF, R_{EF} is 13kΩ to 90kΩ.

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The plots in 図 6-5 and 図 6-6 show delay time settings as function of CS voltage and K_{EF} for two different conditions: R_{EF} = 13kΩ (図 6-5) and R_{EF} = 90kΩ (図 6-6)

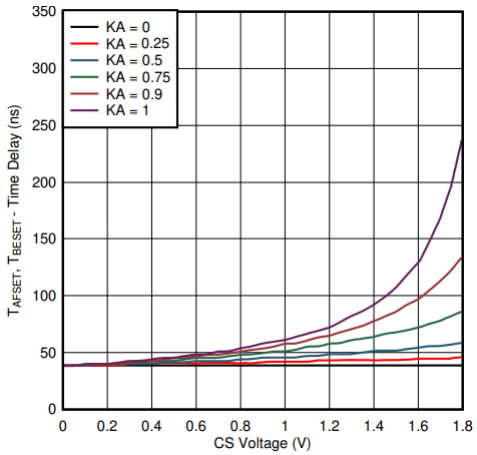

図 6-5. Delay Time T_{AFSET} and T_{BESET} (Over CS Voltage and Selected K_{EF} for R_{EF} Equal 13kΩ)

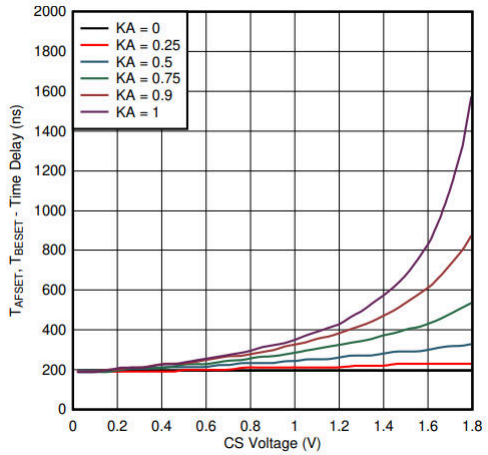

図 6-6. Delay Time T_{AFSET} and T_{BESET} (Over CS Voltage and Selected K_{EF} for R_{EF} Equal 90kΩ)

6.3.8 Minimum Pulse (TMIN)

The resistor R_{TMIN} from the TMIN pin to GND sets a fixed minimum pulse width. This pulse is applied to the transformer and enables ZVS at light load. If the output PWM pulse demanded by the feedback loop is shorter than TMIN, then the controller proceeds to burst mode operation where an even number of TMIN pulses are followed by the off time dictated by the feedback loop. The proper selection of the TMIN duration is dictated by the time it takes to raise sufficient magnetizing current in the power transformer to maintain ZVS. The TMIN pulse is measured from the rising edge of OUTA to the falling edge of OUTD – or from the rising edge of OUTB to the falling edge of OUTC. The minimum pulse TMIN is then defined by 式 8.

$$TMIN = \left(5.92 \times R_{TMIN}\right) ns \tag{8}$$

where

- TMIN is in ns
- R_{TMIN} is in kΩ

Various propagation and response time delays in the power circuit modify (usually increase) the pulse width that is measured at the transformer. Select the correct TMIN setting using an iterative process due to the propagation and response time delays in the power circuit.

注

The minimum allowed resistance on the TMIN pin, R_{TMIN} is 10kΩ.

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The related plot is shown in 図 6-7.

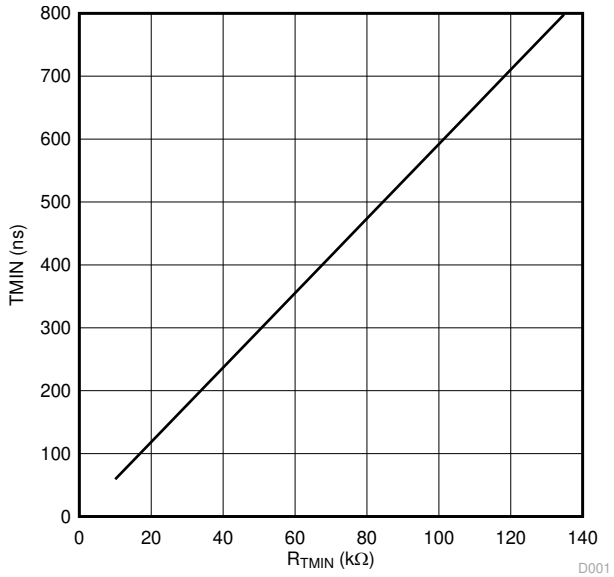

図 6-7. Minimum Time TMIN Over Setting Resistor R_{TMIN}

The value of minimum duty cycle D_{MIN} is determined by 式 9.

$$DMIN = \left(TMIN \times F_{SW(osc)} \times 10^{-4}\right)\% \quad (9)$$

where

- $F_{SW(osc)}$ is oscillator frequency in kHz
- TMIN is the minimum pulse in ns
- and DMIN is in percent

6.3.9 Burst Mode

If the converter is commanding a duty cycle lower than TMIN, then the controller will go into Burst Mode. The controller will always deliver an even number of power cycles to the power transformer. The controller always stops its bursts with an OUTB and an OUTC power delivery cycle. If the controller is still demanding a duty cycle less than TMIN, then the controller goes into shut down mode. Then it waits until the converter is demanding a duty cycle equal or higher than TMIN before the controller puts out TMIN or a PWM duty cycle as dictated by COMP voltage pin.

6.3.10 Switching Frequency Setting

Connecting an external resistor R_T between the RT pin and VREF pins sets the fixed frequency operation and configures the controller as a leader providing synchronization output pulses at SYNC pin with 0.5 duty cycle and frequency equal to the internal oscillator. Connect an external resistor RT between the RT and GND pins to configure the controller as a follower. When the controller is used in follower mode, connect a 825kΩ ±5% resistor from the SS pin to the ground pin in parallel with the SS_EN capacitor. The follower controller operates with 90° phase shift relative to the leader converter if their SYNC pins are tied together. The switching frequency of the converter is equal to the frequency of output pulses.

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式 10 defines the nominal switching frequency of the converter configured as a leader (resistor R_T between the RT pin and VREF). On the UCC2895x there is an internal clock oscillator frequency which is twice as that of the controller's output frequency.

$$F_{SW(nom)} = \left(\frac{2.5 \times 10^3}{\left(\frac{R_T}{V_{REF} - 2.5\,V} + 1 \times \frac{k\Omega}{V} \right)} \right) kHz \quad (10)$$

where

- R_T is in kΩ
- VREF is in volts
- $F_{SW(nom)}$ is in kHz

This is also an empirical approximation and thus, there is no unit agreement. Assume for example, VREF = 5V, R_T = 65kΩ. Then the switching frequency $F_{SW(nom)}$ is going to be 92.6kHz.

式 11 defines the nominal switching frequency of converter if the converter configured as a follower and the resistor R_T is connected between the RT pin and GND.

$$F_{SW(nom)} = \left(\frac{2.5 \times 10^3}{\left(\frac{R_T}{2.5\,V} + 1 \times \frac{k\Omega}{V} \right)} \right) kHz \quad (11)$$

where

- R_T is in kΩ
- $F_{SW(nom)}$ is in kHz

Notice that for VREF = 5V, 式 10 and 式 11 yield the same results.

The plot in 図 6-8 shows how $F_{SW(nom)}$ depends on the resistor R_T value when the VREF = 5V. As it is seen from 式 10 and 式 11, the switching frequency $F_{SW(nom)}$ is set to the same value for either leader or follower configuration provided the same resistor value R_T is used.

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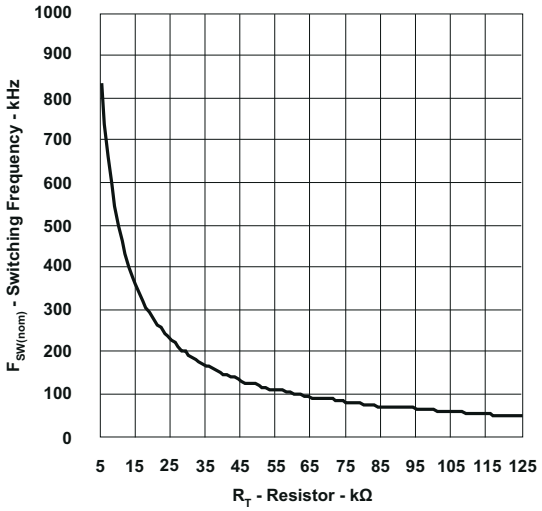

図 6-8. Converter Switching Frequency $F_{SW(nom)}$ Over Resistor R_T Value

6.3.11 Slope Compensation (R_{SUM})

Slope compensation prevents a sub-harmonic oscillation in the controller during in peak current mode (PCM) control operation or during cycle-by-cycle current limit at duty cycles above 50% (some publications suggest it may happen at D < 50%). Slope compensation in the controller adds an additional ramp signal to the CS signal and is applied to:

- the PWM comparator in the case of peak current mode control
- the input of the cycle-by-cycle comparator

At low duty cycles and light loads, the slope compensation ramp reduces the noise sensitivity during peak current mode control operation.

Placing a resistor from the R_{SUM} pin to ground allows the controller to operate in PCM control. Connecting a resistor from R_{SUM} to VREF switches the controller to voltage mode control (VMC) with the internal PWM ramp. In VMC the resistor at R_{SUM} provides CS signal slope compensation for operation in cycle-by-cycle current limit. That is, in VMC, the slope compensation is applied only to the cycle-by-cycle comparator while in PCM the slope compensation is applied to both the PWM and cycle-by-cycle current limit comparators. The operation logic of the slope compensation circuit is shown in 図 6-9.

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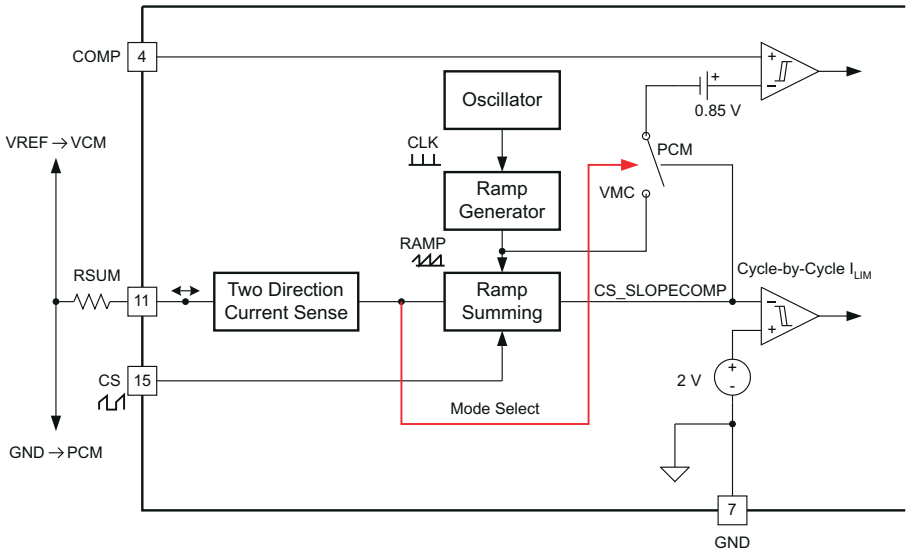

図 6-9. The Operation Logic of Slope Compensation Circuit

Too much slope compensation reduces the benefits of PCM control. In the case of cycle-by-cycle current limit, the average current limit becomes lower and this might reduce the start-up capability into large output capacitances.

The optimum compensation ramp varies, depending on duty cycle, L_{OUT} and L_{MAG}. A good starting point in selecting the amount of slope compensation is to set the slope compensation ramp to be half the inductor current ramp downslope (inductor current ramp during the off time). The inductor current ramp downslope (as seen at the CS pin input, and neglecting the effects of any filtering at the CS pin) is calculated in 式 12:

$$m_o = \frac{V_{OUT}}{L_{OUT}} \times \frac{R_{CS}}{a1 \times CT_{RAT}} \tag{12}$$

where

- V_{OUT} is the output voltage of the converter
- L_{OUT} is the output inductor value
- a1 is the transformer turns ratio (N_P/N_S)
- CT_{RAT} is the current transformer ratio (I_P/I_S, typically 100:1)

Selection of L_{OUT}, a1 and CT_{RAT} are described later in this document. The total slope compensation is $0.5m_0$. Some of this ramp is due to magnetizing current in the transformer, the rest is added by an appropriately chosen resistor from RSUM to ground.

The slope of the additional ramp, me, added to the CS signal by placing a resistor from RSUM to ground is defined by 式 13.

$$me = \left(\frac{2.5}{0.5 \times R_{SUM}} \right) \frac{V}{\mu s} \tag{13}$$

where

- R_{SUM} is in kΩ
- me is in V/μs

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If the resistor from the RSUM pin is connected to the VREF pin, then the controller operates in voltage mode control, still having the slope compensation ramp added to the CS signal used for cycle-by-cycle current limit. In this case the slope is defined by 式 14.

$$me = \left(\frac{(V_{REF} - 2.5\,V)}{0.5 \times R_{SUM}} \right) \frac{V}{\mu s} \tag{14}$$

where

- VREF is in volts
- R_{SUM} is in kΩ
- me is in V/µs

These are empirically derived equations without units agreement. As an example, substituting VREF = 5V and R_{SUM} = 40kΩ, yields the result 0.125V/µs. The related plot of me as a function of R_{SUM} is shown in 図 6-10, Because VREF = 5V, the plots generated from 式 13 and 式 14 coincide.

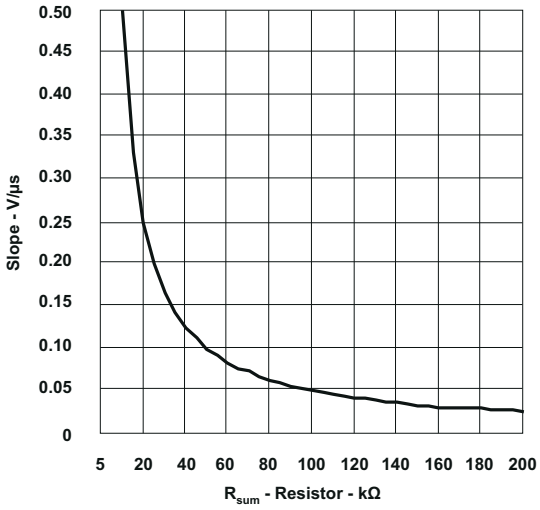

図 6-10. Slope of the Added Ramp Over Resistor R_{SUM}

注

The recommended resistor range for R_{SUM} is 10kΩ to 1MΩ.

6.3.12 Dynamic SR ON/OFF Control (DCM Mode)

The voltage at the DCM pin provided by the resistor divider R_{DCMHI} between VREF pin and DCM, and R_{DCM} from DCM pin to GND, sets the percentage of 2V current limit threshold for the Current Sense pin, (CS). If the CS pin voltage falls below the DCM pin threshold voltage, then the controller initiates the light load power saving mode, and shuts down the synchronous rectifiers, OUTE and OUTF. If the CS pin voltage is higher than the DCM pin threshold voltage, then the controller runs in CCM mode. Connecting the DCM pin to VREF makes the controller run in DCM mode and shuts both Outputs OUTE and OUTF. Shorting the DCM pin to GND disables the DCM feature and the controller runs in CCM mode under all conditions.

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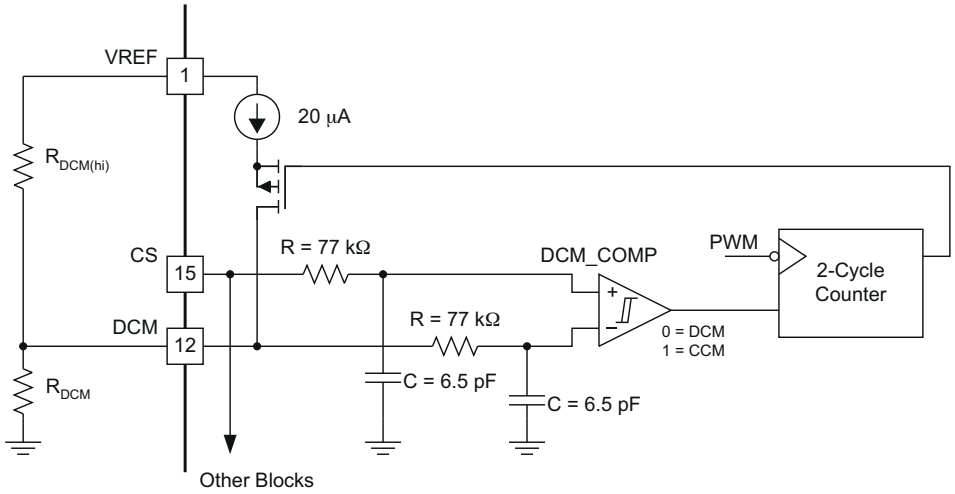

図 6-11. DCM Functional Block

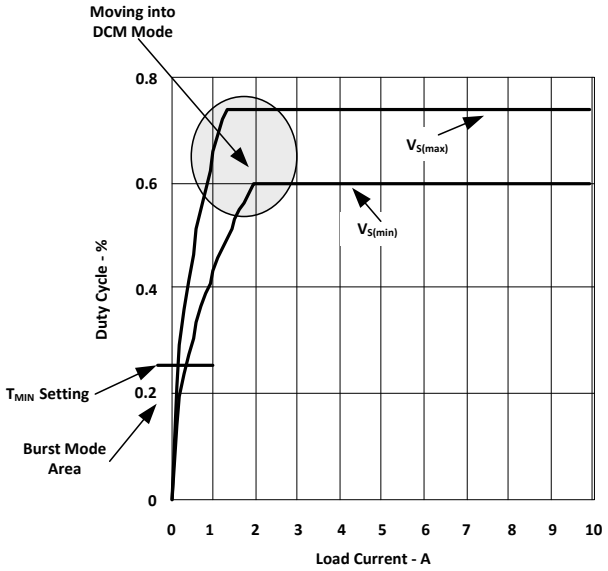

図 6-12. Duty Cycle Change Over Load Current Change

A nominal 20µA switched current source is used to create hysteresis. The current source is active only when the system is in DCM Mode. Otherwise, it is inactive and does not affect the node voltage. Therefore, when in the DCM region, the DCM threshold is the voltage divider plus ΔV explained in 式 15. When in the CCM region, the threshold is the voltage set by the resistor divider. When the CS pin reaches the threshold set on the DCM pin, the system waits to see two consecutive falling edge PWM cycles before switching from CCM to DCM and vice-versa. The magnitude of the hysteresis is a function of the external resistor divider impedance. The hysteresis can be calculated using 式 15:

$$\Delta V = 2 \times 10^{-5} \frac{R_{DCMHI} \times R_{DCM}}{R_{DCMHI} + R_{DCM}} \quad (15)$$

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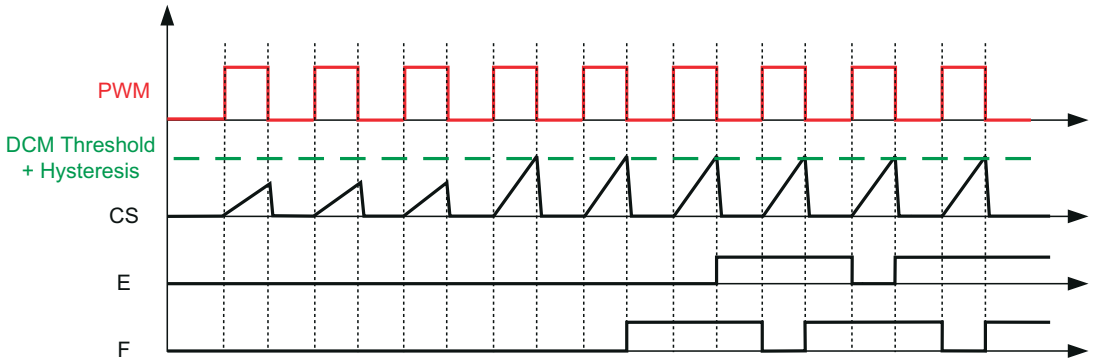

図 6-13. Moving From DCM to CCM Mode

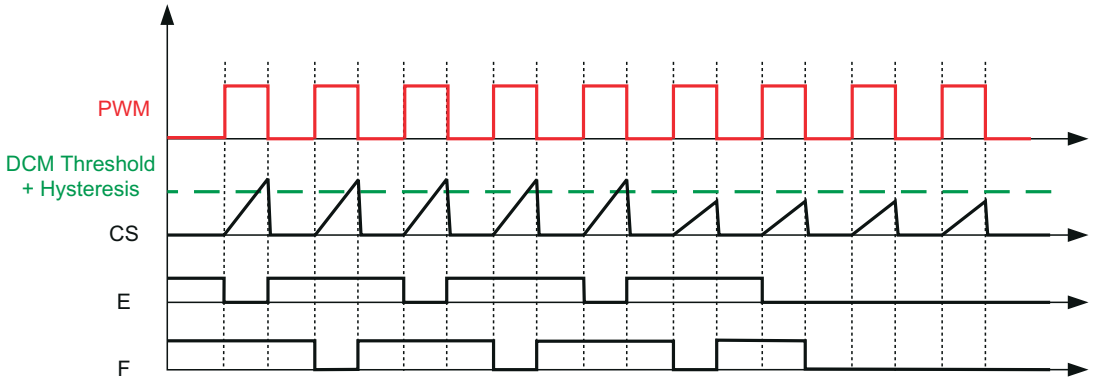

図 6-14. Moving From CCM to DCM Mode

DCM must be used to prevent reverse current in the output inductor which could cause the synchronous FETS to fail.

The controller must switch to DCM mode at a level where the output inductor current is positive. If the output inductor current is negative when the controller switches to DCM mode then the synchronous FETs will see a large V_{DS} spike and may fail.

6.3.13 Current Sensing (CS)

The signal from the current sense pin is used for cycle-by-cycle current limit, peak-current mode control, light-load efficiency management and setting the delay time for outputs OUTA, OUTB, OUTC, OUTD and delay time for outputs OUTE, OUTF. Connect the current sense resistor R_{CS} between CS and GND. Depending on layout, to prevent a potential electrical noise interference, TI recommends pulling a small R-C filter between the R_{CS} resistor and the CS pin. There is a 200Ω pulldown at the CS pin which is turned on after the PWM comparator has tripped. This helps to reset the CS signal prior to the following switching cycle.

6.3.14 Cycle-by-Cycle Current Limit Current Protection and Hiccup Mode

The cycle-by-cycle current limit provides peak current limiting on the primary side of the converter when the load current exceeds its predetermined threshold. For peak current mode control, a certain leading edge blanking time is needed to prevent the controller from false tripping due to switching noise. An internal 30ns filter at the CS input is provided. The total propagation delay TCS from CS pin to outputs is 100ns. An external RC filter is still needed if the power stage requires more blanking time. The 2.0V ±3% cycle-by-cycle current limit threshold is optimized for efficient current transformer based sensing. The duration when a converter operates at cycle-by-cycle current limit depends on the value of soft-start capacitor and how severe the overcurrent condition is. This is achieved by the internal discharge current I_{DS} 式 16 and 式 17 at SS pin.

$$I_{DS(leader)} = (-25 \times (1 - D) + 5)\ \mu A \quad (16)$$

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$$I_{DS(follower)} = (-25 \times (1 - D))\ \mu A \quad (17)$$

The soft-start capacitor value also determines the so-called hiccup mode off-time duration. The behavior of the converter during different modes of operation, along with related soft-start capacitor charge and discharge currents are shown in 図 6-15.

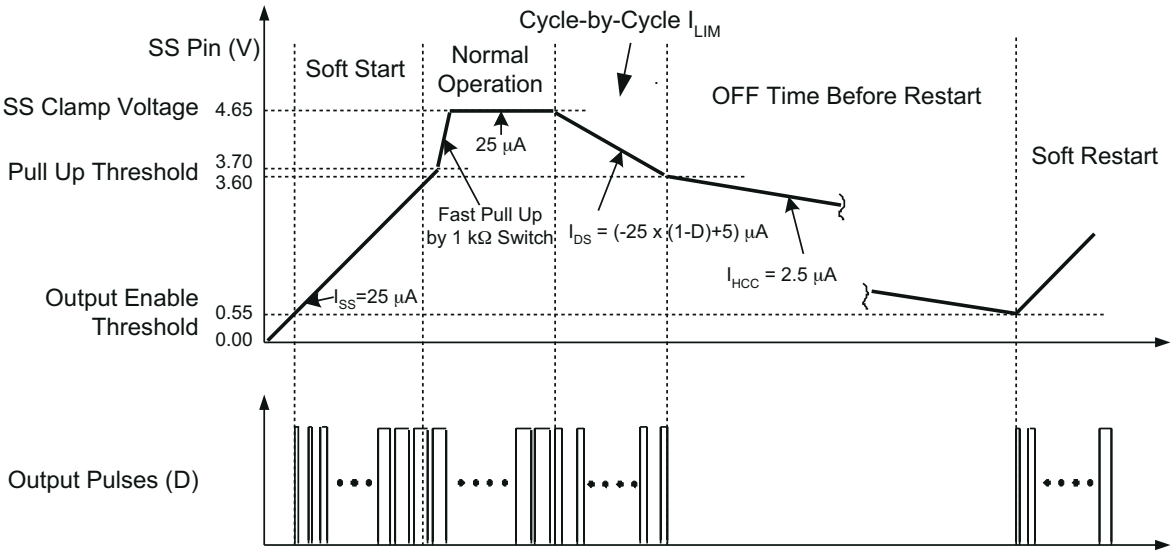

図 6-15. Timing Diagram of Soft-Start Voltage V_{SS}

The largest discharge current of 20µA is when the duty cycle is close to zero. This current sets the shortest operation time during the cycle-by-cycle current limit and is defined in 式 18 and 式 19

$$T_{CL(on\_leader)} = \frac{C_{SS} \times (4.65\ V - 3.7\ V)}{20\ \mu A} \quad (18)$$

$$T_{CL(on\_follower)} = \frac{C_{SS} \times (4.65\ V - 3.7\ V)}{25\ \mu A} \quad (19)$$

Thus, if the soft-start capacitor C_{SS} = 100nF is selected, then the $T_{CL(on)}$ time is 5ms.

To calculate the hiccup off time $T_{CL(off)}$ before the restart, use 式 20 or 式 21.

$$T_{CL(off\_leader)} = \frac{C_{SS} \times (3.6V - 0.55V)}{2.5\mu A} \quad (20)$$

$$T_{CL(off\_follower)} = \frac{C_{SS} \times (3.6V - 0.55V)}{4.9\mu A} \quad (21)$$

With the same soft-start capacitor value at 100nF, the off-time before the restart is 122ms. If the overcurrent condition occurs before the soft-start capacitor voltage reaches the 3.7V threshold during start-up, the controller limits the current but the soft-start capacitor continues to be charged. As soon as the 3.7V threshold is reached, the soft-start voltage is quickly pulled up to the 4.65V threshold by an internal 1kΩ $R_{DS(on)}$ switch and the cycle-by-cycle current limit duration timing starts by discharging the soft-start capacitor. Depending on specific design requirements, the user can override this default behavior by applying external charge or discharge currents to the soft-start capacitor. The whole cycle-by-cycle current limit and hiccup operation is shown in 図 6-15. In this example, the cycle-by-cycle current limit lasts about 5ms followed by 122ms of off-time.

Similarly to the overcurrent condition, the hiccup mode with the restart can be disabled by the user if a pullup resistor of 261kΩ is connected between the SS and VREF pins. The controller remains in the latch-off mode if an

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overcurrent condition occurs. In this case, calculate an external soft-start capacitor value with the additional pullup current taken into account. The latch-off mode can be reset externally if the soft-start capacitor is forcibly discharged below 0.55V or the V_{DD} voltage is lowered below the UVLO threshold.

6.3.15 Synchronization (SYNC)

The UCC2895x allows flexible configuration of converters operating in synchronized mode by connecting all SYNC pins together and by configuration of the controllers as leader and/or followers. The controller configured as leader (resistor between RT and VREF) provides synchronization pulses at the SYNC pin with the frequency equal to 2X the converter frequency $F_{SW(nom)}$ and 0.5 duty cycle. The controller configured as a follower (resistor between RT and GND and 825-kΩ resistor between SS_EN pin to GND) does not generate the synchronization pulses. The follower controller synchronizes its own clock to the falling edge of the synchronization signal thus operating 90° phase shifted versus the leader converter's frequency $F_{SW(nom)}$.

The output inductor in a full bridge converter sees a switching frequency which is twice that seen by the transformer. In the case of the UCC2895x this means that the output inductor operates at 2 × $F_{SW(nom)}$. This means that the 90° phase shift between leader and follower controllers gives a 180° phase shift between the currents in the output inductors and hence maximum ripple cancellation. For more information about synchronizing more than two UCC2895x devices, see *Synchronizing Three or More UCC28950 Phase-Shifted, Full-Bridge Controllers* (SLUA609).

If the synchronization feature is not used then the SYNC pin may be left floating, but connecting the SYNC pin to GND through a 10kΩ resistor will reduce noise pickup and switching frequency jitter.

- If any converter is configured as a follower, the SYNC frequency must be greater than or equal to 1.8 times the converter frequency.
- follower converter does not start until at least one synchronization pulse has been received.
- If any or all converters are configured as followers, then each converter operates at its own frequency without synchronization after receiving at least one synchronization pulse. Thus, If there is an interruption of synchronization pulses at the follower converter, then the controller uses its own internal clock pulses to maintain operation based on the R_T value that is connected to GND in the follower converter.
- In leader mode, SYNC pulses start after SS pin passes its enable threshold which is 0.55 V.
- follower starts generating SS/EN voltage even though synchronization pulses have not been received.
- TI recommends that the SS on the leader controller starts before the SS on the follower controller; therefore SS/EN pin on leader converter must reach its enable threshold voltage before SS/EN on the follower converter starts for proper operation. On the same note, TI also recommends that the T_{MIN} resistors on both leader and follower are set at the same value.

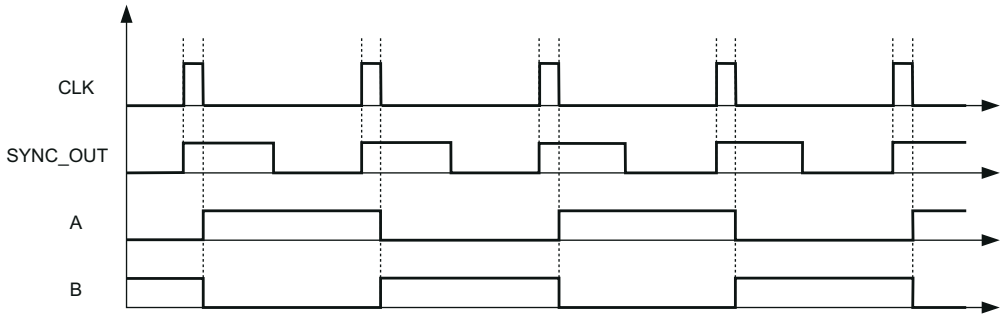

図 6-16. SYNC_OUT (leader Mode) Timing Diagram

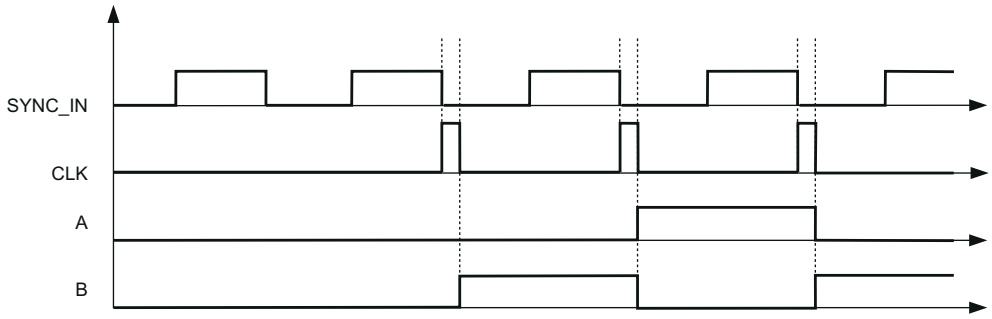

図 6-17. SYNC_IN (follower Mode) Timing Diagram

6.3.16 Outputs (OUTA, OUTB, OUTC, OUTD, OUTE, OUTF)

- All MOSFET control outputs have 0.2A drive capability.
- The control outputs are configured as P-MOS and N-MOS totem poles with typical $R_{DS(on)}$ 20Ω and 10Ω, accordingly.
- The control outputs are capable of charging 100pF capacitor within 12ns and discharge within 8ns.
- The amplitude of output control pulses is equal to V_{DD}.
- Control outputs are designed to be used with external gate MOSFET/IGBT drivers.
- The design is optimized to prevent the latch-up of outputs and verified by extensive tests.

The UCC2895x controlers has outputs OUTA, OUTB driving the active leg, initiating the duty cycle leg of power MOSFETs in a phase-shifted full bridge power stage, and outputs OUTC, OUTD driving the passive leg, completing the duty cycle leg, as it is shown in the typical timing diagram in 図 7-1. Outputs OUTE and OUTF are optimized to drive the synchronous rectifier MOSFETs (see 図 7-3). These outputs have 200mA peak-current capabilities and are designed to drive relatively small capacitive loads like inputs of external MOSFET or IGBT drivers. Recommended load capacitance should not exceed 100pF. The amplitude of the output signal is equal to the V_{DD} voltage.

6.3.17 Supply Voltage (VDD)

Connect this pin to a bias supply in the range from 8V to 17V. Place high-quality, low ESR and ESL and at least 1µF ceramic bypass capacitor C_{VDD} from this pin to GND. TI recommends using a 10Ω resistor in series from the bias supply to the VDD pin to form an RC filter with the C_{VDD} capacitor.

6.3.18 Ground (GND)

All signals are referenced to this node. TI recommends having a separate quiet analog plane connected in one place to the power plane. The analog plane connects the components related to the pins VREF, EA+, EA-, COMP, SS/EN, DELAB, DELCD, DELEF, TMIN, RT, RSUM. The power plane connects the components related to the pins DCM, ADELEF, ADEL, CS, SYNC, OUTF, OUTE, OUTD, OUTC, OUTB, OUTA, and VDD. 図 6-18 shows an example of layout and ground planes connection.

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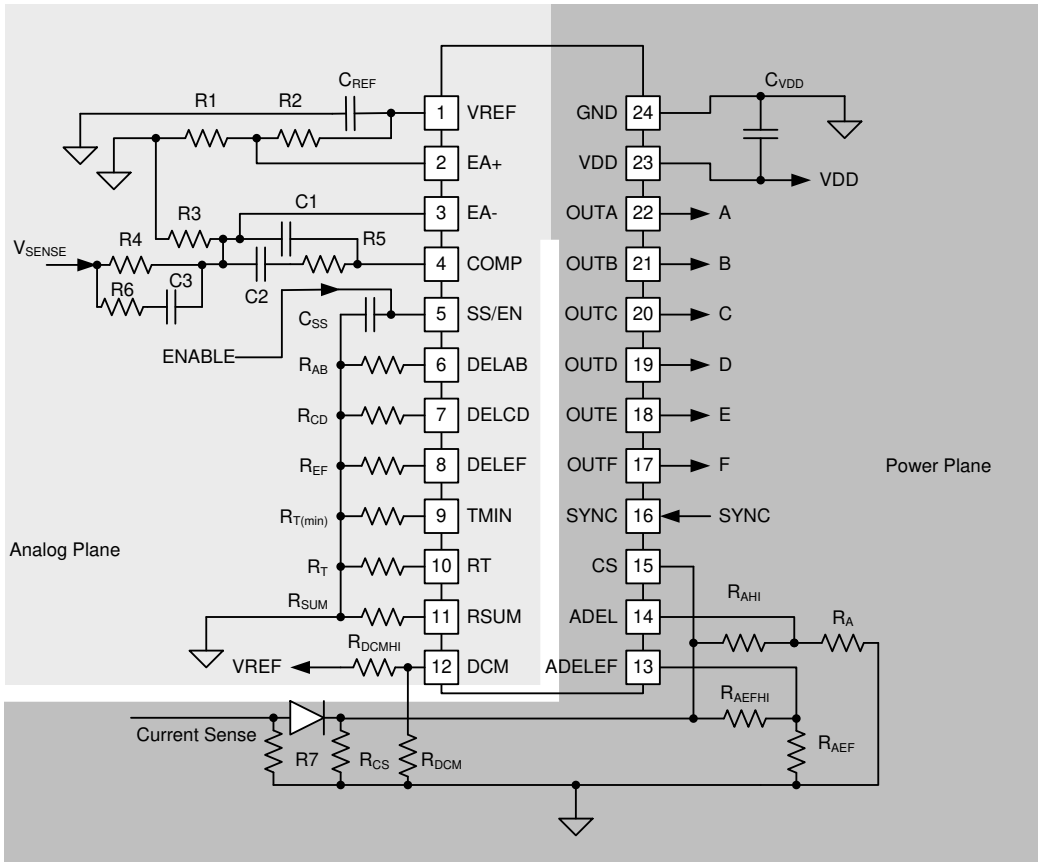

図 6-18. Layout Recommendation for Analog and Power Planes

6.4 Device Functional Modes

The UCC2895x controllers offer many operational modes. These modes are described in detail in *セクション 6.3*.

- Current mode[1]. The UCC2895x controller operates in current mode control when the RSUM pin is connected to GND through a resistor (R_{SUM}) . The resistor sets the amount of slope compensation.
- Voltage mode[1]. The controller operates in voltage mode control when the RSUM pin is connected to VREF through a resistor (R_{SUM}). The chosen resistor value gives the correct amount of slope compensation for operation in current limit mode (cycle-by-cycle current limit).
- DCM mode. The controller enters DCM mode when the signal at the CS pin falls below the level set by the resistor at the DCM pin. The SR drives (OUTE and OUTF) turn off and secondary rectification occurs through the body diodes of the SRs.
- Burst mode. The controllers enter burst mode when the pulse width demanded by the feedback signal falls below the width set by the resistor at the TMIN pin.
- Leader mode. This is the default operation mode of the controller and is used when there is only one UCC2895x controller in the system. Connect the timing resistor (R_T) from the RT pin to VREF. In a system with more than one UCC2895x controller, configure one as the leader and the others as followers[1].
- Follower mode. The follower controller operates with a 90° phase shift relative to the leader (providing their SYNC pins are tied together). Connect the timing resistor (R_T) from the RT pin to GND and connect an 825kΩ ±5% resistor from the SS/EN pin to GND[1].
- Synchronized mode. When a UCC2895x controller is configured as a follower, its SYNC pin is used as an input. The follower synchronizes its internal oscillator at 90° to the signal at its SYNC pin. The application note, *Synchronizing Three or More UCC28950 Phase-Shifted, Full-Bridge Controllers*, discusses how multiple follower controllers may be synchronized to a single leader oscillator.
- Hiccup mode. This mode provides overload protection to the power circuit. The UCC2895x controller stops switching after a certain time in current limit. It starts again (soft-start) after a delay time. The user can control the time spent in current limit before switching is stopped and the delay time before the soft start happens.
- Current-limit mode. The UCC2895xc ontroller provides cycle-by-cycle current limiting when the signal at the CS pin reaches 2V.
- Latch-off mode. Connect a resistor between the SS pin and VREF. The UCC2895x controller then latches off when the controller enterscurrent-limit mode. [1]

[1] Current mode control and voltage mode control are mutually exclusive as are leader and follower modes.

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7 Application and Implementation

注

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7.1 Application Information

The high efficiency of a phase-shifted full-bridge DC-DC converter using the UCC2895x is achieved by using synchronous rectification, a control algorithm providing ZVS condition over the entire load current range, accurate adaptive timing of the control signals between primary and secondary FETs and special operating modes at light load. A simplified electrical diagram of this converter is shown in 図 7-3. The UCC2895xcontroller is located on the secondary side of converter, although it could be placed on the primary side as well. The secondary side lication allows easy power system level communication and better handling of some transient conditions that require fast direct control of the synchronous rectifier MOSFETs. The power stage includes primary side MOSFETs, QA, QB, QC, QD and secondary side synchronous rectifier MOSFETs, QE and QF. For example, for the 12-V output converters in server power supplies use of the center-tapped rectifier scheme with L-C output filter is a popular choice.

To maintain high efficiency at different output power conditions, the converter operates in synchronous rectification mode at mid and high output power levels, transitioning to diode rectifier mode at light load and then into burst mode as the output power becomes even lower. All of these transitions are based on current sensing on the primary side using a current sense transformer in this specific case.

The major waveforms of the phase-shifted converter during normal operation are shown in 図 7-1. The upper six waveforms in 図 7-1 show the output drive signals of the controller. In normal mode, the outputs OUTE and OUTF overlap during the part of the switching cycle when both rectifier MOSFETs are conducting and the windings of the power transformer are shorted. Current, I_{PR}, is the current flowing through the primary winding of the power transformer. The bottom four waveforms show the drain-source voltages of rectifier MOSFETs, V_{DS_QE} and V_{DS_QF}, the voltage at the output inductor, V L_{OUT}, and the current through the output inductor, I L_{OUT}. Proper timing between the primary switches and synchronous rectifier MOSFETs is critical to achieve highest efficiency and reliable operation in this mode. The controller adjusts the turn OFF timing of the rectifier MOSFETs as a function of load current to ensure minimum conduction time and reverse recovery losses of their internal body diodes.

ZVS is an important feature of relatively high input voltage converters in reducing switching losses associated with the internal parasitic capacitances of power switches and transformers. The controller ensures ZVS conditions over the entire load current range by adjusting the delay time between the primary MOSFETs switching in the same leg in accordance to the load variation. The controller also limits the minimum ON-time pulse applied to the power transformer at light load, allowing the storage of sufficient energy in the inductive components of the power stage for the ZVS transition.

As the load current reduces from full load down to the no-load condition, the controller selects the most efficient power saving mode by moving from the normal operation mode to the discontinuous-current diode-rectification mode and, eventually, at very light-load and at no-load condition, to the burst mode. These modes and related output signals, OUTE, OUTF, driving the rectifier MOSFETs, are shown in 図 7-2.

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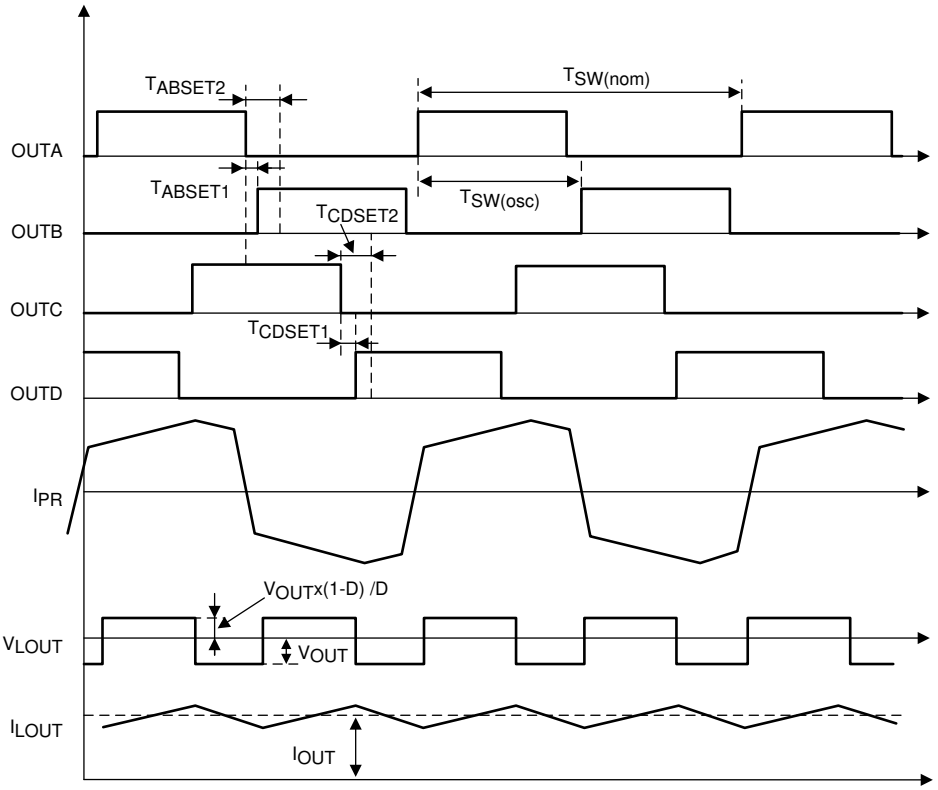

図 7-1. Phase-Shifted Converter Waveforms

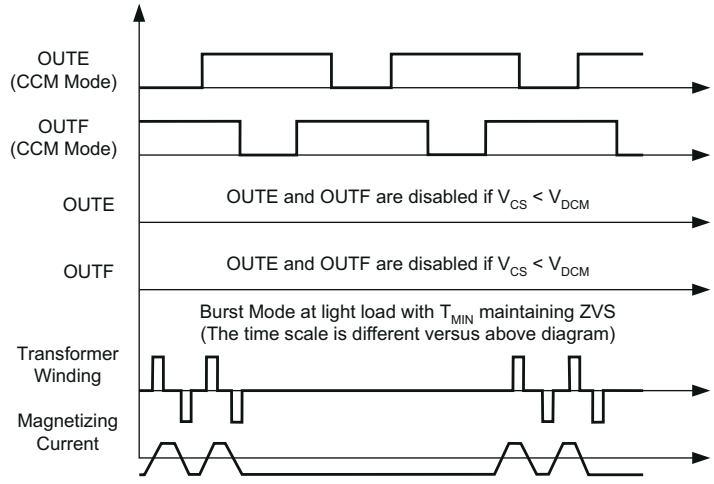

図 7-2. Major Waveforms During Transitions Between Different Operating Modes

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It is necessary to prevent the reverse current flow through the synchronous rectifier MOSFETs and output inductor at light load, during parallel operation and at some transient conditions. Such reverse current results in circulating of some extra energy between the input voltage source and the load and, therefore, causes increased losses and reduced efficiency. Another negative effect of such reverse current is the loss of ZVS condition. The suggested control algorithm prevents reverse current flow, still maintaining most of the benefits of synchronous rectification by switching off the drive signals of rectifier MOSFETs in a predetermined way. At some pre-determined load current threshold, the controller disables outputs OUTE and OUTF by bringing them down to zero.

Synchronous rectification using MOSFETs requires some electrical energy to drive the MOSFETs. There is a condition below some light-load threshold when the MOSFET drive related losses exceed the saving provided by the synchronous rectification. At such light load, it is best to disable the drive circuit and use the internal body diodes of rectifier MOSFETs, or external diodes in parallel with the MOSFETs, for more efficient rectification. In most practical cases, the drive circuit needs to be disabled close to DCM mode. This mode of operation is called discontinuous-current diode-rectification mode.

At very light-load and no-load conditions, the duty cycle, demanded by the closed-feedback-loop control circuit for output voltage regulation, can be very low. This level leads to the loss of ZVS condition and increased switching losses. To avoid the loss of ZVS, the control circuit limits the minimum ON-time pulse applied to the power transformer using resistor from TMIN pin to GND. Therefore, the only way to maintain regulation at very light load and at no-load condition is to skip some pulses. The controller skips pulses in a controllable manner to avoid saturation of the power transformer. Such operation is called burst mode. In Burst Mode there are always an even number of pulses applied to the power transformer before the skipping off time. Thus, the flux in the core of the power transformer always starts from the same point during the start of every burst of pulses.

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7.2 Typical Application

A typical application for the UCC2895x is a controller for a phase-shifted full-bridge converter that converts a 390V_{DC} input to a regulated 12V output using synchronous rectifiers to achieve high efficiency.

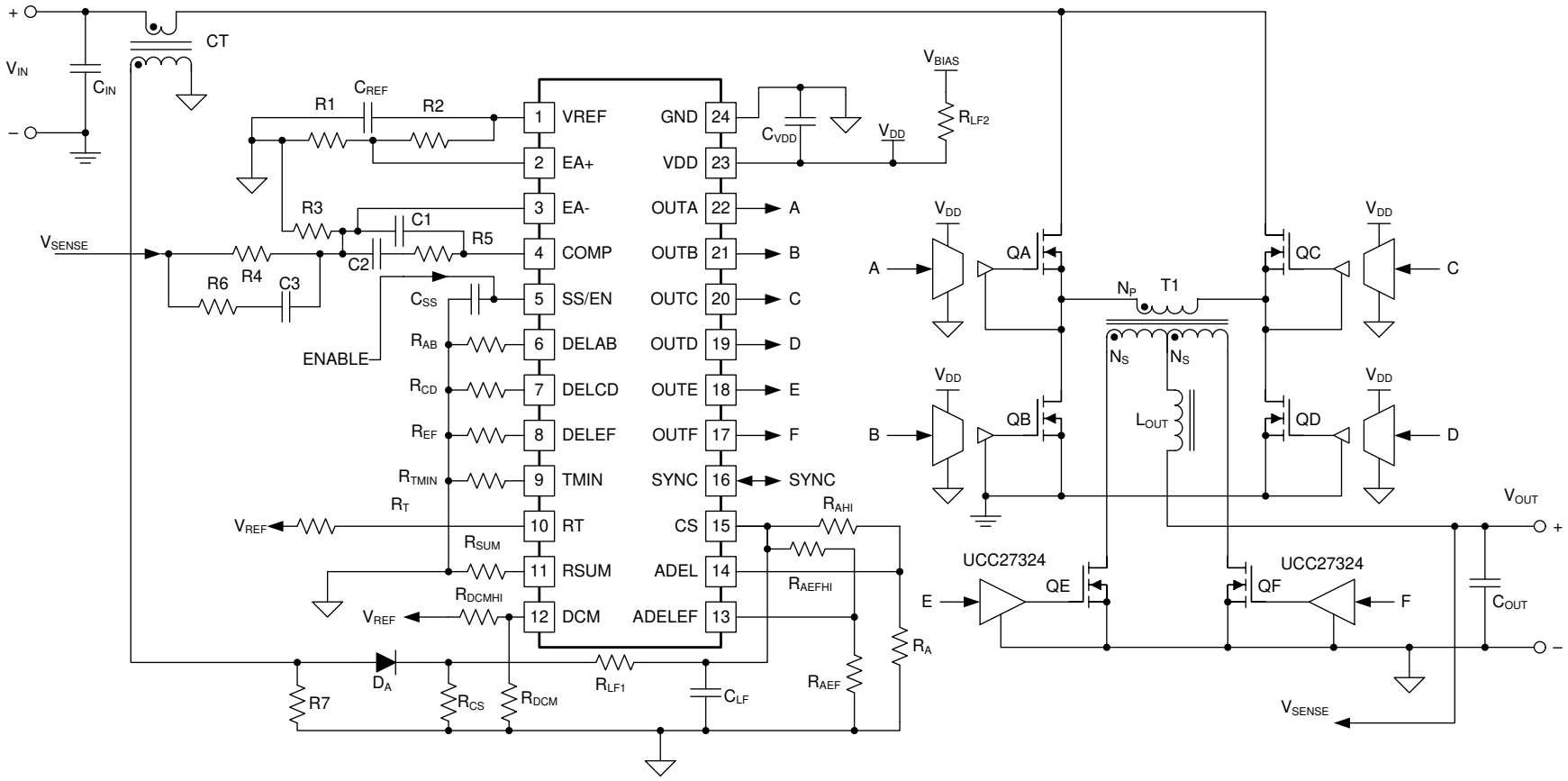

図 7-3. Typical Application

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7.2.1 Design Requirements

表 7-1 lists the requirements for this application.

表 7-1. UCC2895x Typical Application Design Requirements

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT CHARACTERISTICS						
V_{IN}	DC input voltage range		370	390	410	V
$I_{IN(max)}$	Maximum input current	V_{IN}= 370V_{DC} to 410V_{DC}			2	A
OUTPUT CHARACTERISTICS						
V_{OUT}	Output voltage	V_{IN}= 370V_{DC} to 410V_{DC}	11.4	12	12.6	V
I_{OUT}	Output current	V_{IN}= 370V_{DC} to 410V_{DC}			50	A
	Output voltage transient	90% load step		600		mV
P_{OUT}	Continuous output power	V_{IN}= 370V_{DC} to 410V_{DC}			600	W
	Load regulation	V_{IN} = 370V_{DC} to 410V_{DC}, I_{OUT}= 5A to 50A			140	mV
	Line regulation	V_{IN} = 370V_{DC} to 410V_{DC}, I_{OUT}= 5A to 50A			140	mV
	Output ripple voltage	V_{IN} = 370V_{DC} to 410V_{DC}, I_{OUT}= 5A to 50A			200	mV
SYSTEM						
F_{SW}	Switching Frequency			100		kHz
	Full-load efficiency	V_{IN}= 370V_{DC} to 410V_{DC}, P_{OUT}= 500W	93%	94%		

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7.2.2 Detailed Design Procedure

In high-power server applications to meet high-efficiency and green standards some power-supply designers have found it easier to use a phase-shifted, full-bridge converter. This is because the phase-shifted, full-bridge converter can obtain zero-voltage switching on the primary side of the converter, reducing switching losses, and EMI and increasing overall efficiency.

This is a review of the design of a 600-W, phase-shifted, full-bridge converter for one of these power systems using the UCC2895x device, which is based on typical values. In a production design, the values may need to be modified for worst-case conditions. TI has provided a MathCAD Design Tool and an Excel Design Tool to support the system designer. Both tools can be accessed in the *Tools and Software* tab of the UCC2895x product folder on TI.com, or can be downloaded through the following links: MathCAD Design Tool, *Excel Design Tool*.

注

The term f_{SW} refers to the switching frequency applied to the power transformer. The output inductor experiences a switching frequency that is 2 × f_{SW} .

7.2.2.1 Power Loss Budget

To meet the efficiency goal, a power loss budget must be set (see 式 22).

$$P_{BUDGET} = P_{OUT} \times \left(\frac{1-\eta}{\eta} \right) \approx 45.2\,W \tag{22}$$

7.2.2.2 Preliminary Transformer Calculations (T1)

Transformer turns ratio (a1) is:

$$a1 = \frac{N_P}{N_S} \tag{23}$$

Estimate FET voltage drop (V_{RDSON}) as: V_{RDSON} = 0.3V

Select transformer turns based on 70% duty cycle (D_{MAX}) at minimum specified input voltage. This will give some room for dropout if a PFC front end is used (see 式 24 and 式 25).

$$a1 = \frac{N_P}{N_S} \tag{24}$$

$$a1 = \frac{(V_{INMIN} - 2 \times V_{RDSON}) \times D_{MAX}}{V_{OUT} + V_{RDSON}} \approx 21 \tag{25}$$

Turn the ratio and round is to the nearest whole turn: a1 = 21

Calculate the typical duty cycle (D_{TYP}) based on average input voltage in 式 26.

$$D_{TYP} = \frac{(V_{OUT} + V_{RDSON}) \times a1}{(V_{IN} - 2 \times V_{RDSON})} \approx 0.66 \tag{26}$$

Output inductor peak-to-peak ripple current is set to 20% of the output current using 式 27.

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$$\Delta I_{LOUT} = \frac{P_{OUT} \times 0.2}{V_{OUT}} = 10\,A \tag{27}$$

Take care in selecting the correct amount of magnetizing inductance (L_{MAG}). 式 28 calculates the minimum magnetizing inductance of the primary of the transformer (T1) to ensure the converter operates in current-mode control. As L_{MAG} reduces, the increasing magnetizing current becomes an increasing proportion of the signal at the CS pin. If the magnetizing current increases enough, it can swamp out the current sense signal across R_{CS} and the converter will operate increasingly as if it were in voltage mode control rather than current mode.

$$L_{MAG} \geq \frac{V_{IN} \times (1 - D_{TYP})}{\frac{\Delta I_{LOUT} \times 0.5}{a1} \times 2 \times F_{SW}} \approx 2.78\,mH \tag{28}$$

図 7-4 shows T1 primary current ($I_{PRIMARY}$) and synchronous rectifiers QE (I_{QE}) and QF (I_{QF}) currents with respect to the synchronous rectifier gate drive currents. I_{QE} and I_{QF} are the same as the secondary winding currents of T1. Variable D is the duty cycle of the converter.

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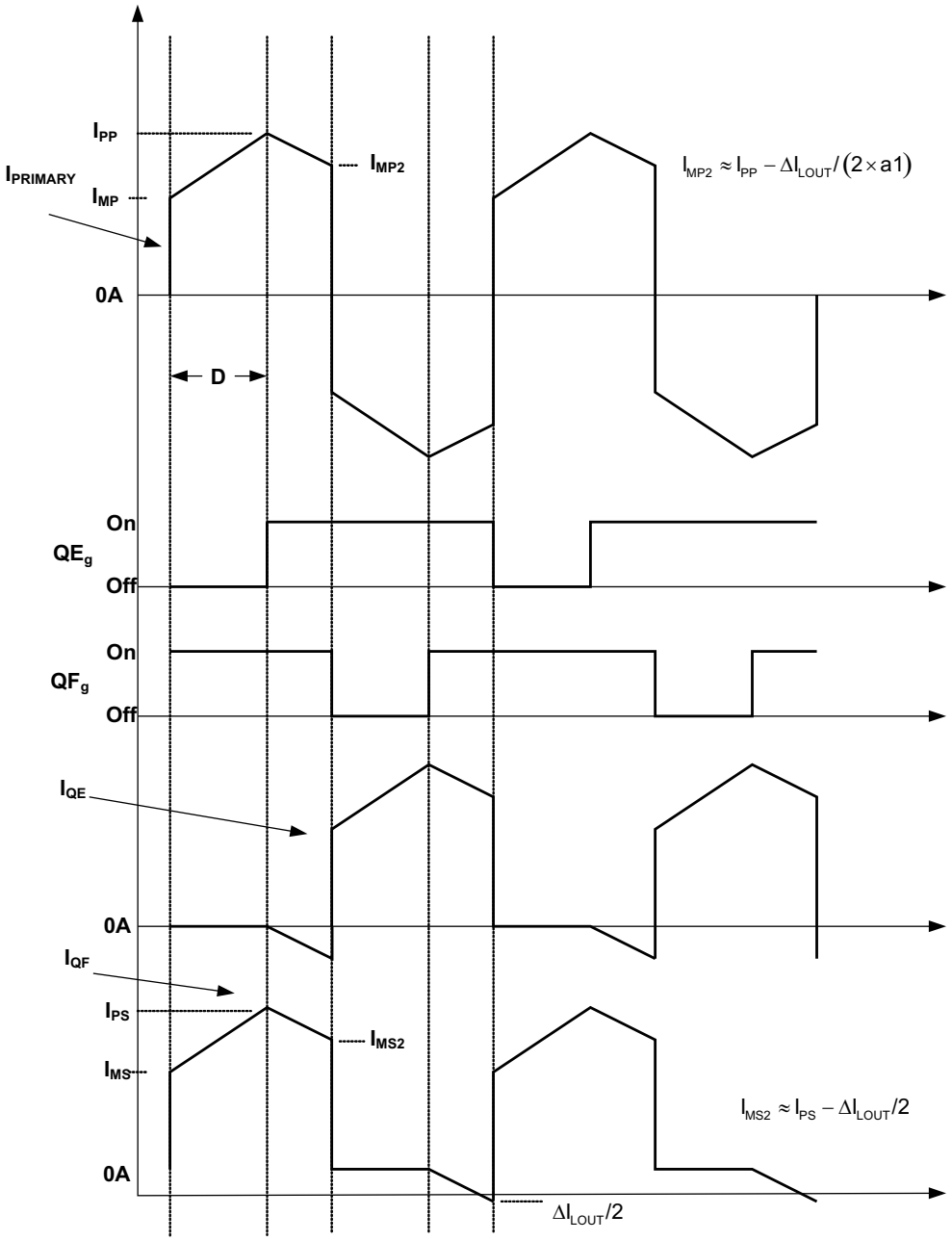

図 7-4. T1 Primary and QE and QF FET Currents

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Calculate T1 secondary RMS current (I_{SRMS}) in 式 29 through 式 31:

$$I_{PS} = \frac{P_{OUT}}{V_{OUT}} + \frac{\Delta I_{LOUT}}{2} \approx 55\,A \tag{29}$$

$$I_{MS} = \frac{P_{OUT}}{V_{OUT}} - \frac{\Delta I_{LOUT}}{2} \approx 45\,A \tag{30}$$

$$I_{MS2} = I_{PS} - \frac{\Delta I_{LOUT}}{2} \approx 50\,A \tag{31}$$

Secondary RMS current (I_{SRMS1}) when energy is being delivered to the secondary (see 式 32):

$$I_{SRMS1} = \sqrt{\left(\frac{D_{MAX}}{2}\right)\left[I_{PS} \times I_{MS} + \frac{\left(I_{PS} - I_{MS}\right)^2}{3}\right]} \approx 29.6\,A \tag{32}$$

Secondary RMS current (I_{SRMS2}) when current is circulating through the transformer when QE and QF are both on (see 式 33).

$$I_{SRMS2} = \sqrt{\left(\frac{1 - D_{MAX}}{2}\right)\left[I_{PS} \times I_{MS2} + \frac{\left(I_{PS} - I_{MS2}\right)^2}{3}\right]} \approx 20.3\,A \tag{33}$$

Secondary RMS current (I_{SRMS3}) caused by the negative current in the opposing winding during freewheeling period calculated in 式 34. Refer to 図 7-4.

$$I_{SRMS3} = \frac{\Delta I_{LOUT}}{2}\sqrt{\left(\frac{1 - D_{MAX}}{2 \times 3}\right)} \approx 1.1A \tag{34}$$

Total secondary RMS current (I_{SRMS}) is calculated in 式 35:

$$I_{SRMS} = \sqrt{I_{SRMS1}^{\,2} + I_{SRMS2}^{\,2} + I_{SRMS3}^{\,2}} \approx 36.0\,A \tag{35}$$

Calculate T1 Primary RMS Current (I_{PRMS}) using 式 36 through 式 40:

$$\Delta I_{LMAG} = \frac{V_{INMIN} \times D_{MAX}}{L_{MAG} \times 2 \times F_{SW}} \approx 0.47\,A \tag{36}$$

$$I_{PP} = \left(\frac{P_{OUT}}{V_{OUT} \times \eta} + \frac{\Delta I_{LOUT}}{2}\right)\frac{1}{a1} + \Delta I_{LMAG} \approx 3.3\,A \tag{37}$$

$$I_{MP} = \left(\frac{P_{OUT}}{V_{OUT} \times \eta} - \frac{\Delta I_{LOUT}}{2}\right)\frac{1}{a1} + \Delta I_{LMAG} \approx 2.8A \tag{38}$$

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$$I_{PRMS1} = \sqrt{(D_{MAX})\left[I_{PP} \times I_{MP} + \frac{(I_{PP} - I_{MP})^2}{3}\right]} \approx 2.5\,A \tag{39}$$

$$I_{MP2} = I_{PP} - \left(\frac{\Delta I_{LOUT}}{2}\right)\frac{1}{a1} \approx 3.0\,A \tag{40}$$

T1 Primary RMS (I_{PRMS1}) current when energy is being delivered to the secondary (see 式 41).

$$I_{PRMS1} = \sqrt{(D_{MAX})\left[I_{PP} \times I_{MP} + \frac{(I_{PP} - I_{MP})^2}{3}\right]} \approx 2.5\,A \tag{41}$$

T1 Primary RMS (I_{PRMS2}) current when the converter is free wheeling. This is calculated in 式 42:

$$I_{PRMS2} = \sqrt{(1 - D_{MAX})\left[I_{PP} \times I_{MP2} + \frac{(I_{PP} - I_{MP2})^2}{3}\right]} \approx 1.7\,A \tag{42}$$

The total T1 primary RMS current (I_{PRMS}) is calculated using 式 43:

$$I_{PRMS} = \sqrt{I_{PRMS1}^{\ 2} + I_{PRMS2}^{\ 2}} \approx 3.1A \tag{43}$$

For this design, a Vitec™ transformer was selected for part number 75PR8107 with the following specifications:

- a1 = 21
- L_{MAG} = 2.8mH
- measured leakage inductance on the Primary (L_{LK}) is 4µH
- transformer Primary DC resistance (DCR_P) is 0.215Ω
- transformer Secondary DC resistance (DCR_S) is 0.58mΩ
- estimated transformer core losses (P_{T1}) calculated in 式 44 are twice the copper loss (which is an estimate and the total losses may vary based on magnetic design)

$$P_{T1} \approx 2 \times \left(I_{PRMS}^{\ 2} \times DCR_P + 2 \times I_{SRMS}^{\ 2} \times DCR_S\right) \approx 7.0\,W \tag{44}$$

Calculate remaining power budget using 式 45:

$$P_{BUDGET} = P_{BUDGET} - P_{T1} \approx 38.1W \tag{45}$$

7.2.2.3 QA, QB, QC, QD FET Selection

In this design to meet efficiency and voltage requirements 20A, 650V, CoolMOS FETs from Infineon are chosen for QA..QD.

The FET drain to source on resistance is:

$$R_{ds(on)QA} = 0.220\,\Omega \tag{46}$$

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The FET Specified C_{OSS} is:

$$C_{OSS\_QA\_SPEC} = 780\,pF \tag{47}$$

The voltage across drain-to-source (V_{dsQA}) where C_{OSS} was measured as a data sheet parameter:

$$V_{dsQA} = 25\,V \tag{48}$$

Calculate average C_{oss} [2] using 式 49:

$$C_{OSS\_QA\_AVG} = C_{OSS\_QA\_SPEC}\sqrt{\frac{V_{dsQA}}{V_{INMAX}}} \approx 193\,pF \tag{49}$$

The QA FET gate charge is:

$$QA_g = 15\,nC \tag{50}$$

The voltage applied to FET gate to activate FET is:

$$V_g = 12\,V \tag{51}$$

Calculate QA losses (P_{QA}) based on $R_{ds(on)QA}$ and gate charge (QA_g) using 式 52:

$$P_{QA} = I_{PRMS}{}^2 \times R_{DS(on)QA} + 2 \times QA_g \times V_g \times f_{SW} \approx 2.1W \tag{52}$$

Recalculate the power budget using 式 53:

$$P_{BUDGET} = P_{BUDGET} - 4 \times P_{QA} \approx 29.7\,W \tag{53}$$

7.2.2.4 Selecting L_S

Calculating the value of the shim inductor (L_S) is based on the amount of energy required to achieve zero voltage switching. This inductor needs to able to deplete the energy from the parasitic capacitance at the switch node. 式 54 selects L_S to achieve ZVS at 100% load down to 50% load based on the primary FET's average total C_{OSS} at the switch node.

注

The actual parasitic capacitance at the switched node may differ from the estimate and L_S may have to be adjusted accordingly.

$$L_S \geq \left(2 \times C_{OSS\_QA\_AVG}\right)\frac{V_{INMAX}{}^2}{\left(\frac{I_{PP}}{2} - \frac{\Delta I_{LOUT}}{2 \times a1}\right)^2} - L_{LK} \approx 26\,\mu H \tag{54}$$

For this design, a 26µH Vitec inductor was chosen for L_S, part number 60PR964. The shim inductor has the following specifications:

$$L_S = 26\,\mu H \tag{55}$$

The L_S DC Resistance is:

$$DCR_{LS} = 27\,m\Omega \tag{56}$$

Estimate L_S power loss (P_{LS}) and readjust remaining power budget using 式 57 through 式 58:

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$$P_{LS} = 2 \times I_{PRMS}^{2} \times DCR_{LS} \approx 0.5\,W \quad (57)$$

$$P_{BUDGET} = P_{BUDGET} - P_{LS} \approx 29.2\,W \quad (58)$$

7.2.2.5 Selecting Diodes D_B and D_C

There is a potential for high voltage ringing on the secondary rectifiers, caused by the difference in current between the transformer and the shim inductor when the transformer comes out of freewheeling. Diodes D_B and D_C provide a path for this current and prevent any ringing by clamping the transformer primary to the primary side power rails. Normally these diodes do not dissipate much power, but must be sized to carry the full primary current. The worse case power dissipated in these diodes is calculated using 式 59:

$$P = 0.5 \times L_S \times I^{2}_{PRMS} \times F_{SW} \quad (59)$$

Choose ultra-fast type diodes rated for the input voltage of the converter – V_{IN} (410VDC in this case).

The MURS360 diode accomodates this power level.

7.2.2.6 Output Inductor Selection (L_{OUT})

Inductor L_{OUT} is designed for 20% inductor ripple current (ΔI_{LOUT}) calculated in 式 60 and 式 61:

$$\Delta I_{LOUT} = \frac{P_{OUT} \times 0.2}{V_{OUT}} = \frac{600\,W \times 0.2}{12\,V} \approx 10\,A \quad (60)$$

$$L_{OUT} = \frac{V_{OUT} \times (1 - D_{TYP})}{\Delta I_{LOUT} \times 2 \times f_{SW}} \approx 2\,\mu H \quad (61)$$

Calculate output inductor RMS current (I_{LOUT_RMS}) using 式 62:

$$I_{LOUT\_RMS} = \sqrt{\left(\frac{P_{OUT}}{V_{OUT}}\right)^{2} + \left(\frac{\Delta I_{LOUT}}{2\sqrt{3}}\right)^{2}} = 50.1A \quad (62)$$

A 2µH inductor from Vitec Electronics Corporation, part number 75PR8108, is suitable for this design. The inductor has the following specifications:

$$L_{OUT} = 2\,\mu H \quad (63)$$

The output inductor DC resistance is:

$$DCR_{LOUT} = 750\,\mu\Omega \quad (64)$$

Estimate output inductor losses (P_{LOUT}) using 式 65 and recalculate the power budget using 式 66. Note P_{LOUT} is an estimate of inductor losses that is twice the copper loss. Note this may vary based on magnetic manufactures. It is advisable to double check the magnetic loss with the magnetic manufacture.

$$P_{LOUT} = 2 \times I_{LOUT\_RMS}^{2} \times DCR_{LOUT} \approx 3.8\,W \quad (65)$$

$$P_{BUDGET} = P_{BUDGET} - P_{LOUT} \approx 25.4\,W \quad (66)$$

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7.2.2.7 Output Capacitance (C_{OUT})

The output capacitor is selected based on holdup and transient (V_{TRAN}) load requirements.

The time it takes L_{OUT} to change 90% of its full load current is calculated in 式 67:

$$t_{HU} = \frac{\frac{L_{OUT} \times P_{OUT} \times 0.9}{V_{OUT}}}{V_{OUT}} = 7.5\,\mu s \tag{67}$$

During load transients most of the current will immediately go through the capacitors equivalent series resistance (ESR_{COUT}). 式 68 and 式 69 are used to select ESR_{COUT} and C_{OUT} based on a 90% load step in current. The ESR is selected for 90% of the allowable transient voltage (V_{TRAN}), while the output capacitance (C_{OUT}) is selected for 10% of V_{TRAN}.

$$ESR_{COUT} \le \frac{V_{TRAN} \times 0.9}{\frac{P_{OUT} \times 0.9}{V_{OUT}}} = 12\,m\Omega \tag{68}$$

$$C_{OUT} \ge \frac{\frac{P_{OUT} \times 0.9 \times t_{HU}}{V_{OUT}}}{V_{TRAN} \times 0.1} \approx 5.6\,mF \tag{69}$$

Before selecting the output capacitor, the output capacitor RMS current (I_{COUT_RMS}) must be calculated using 式 70.

$$I_{COUT\_RMS} = \frac{\Delta I_{LOUT}}{\sqrt{3}} \approx 5.8\,A \tag{70}$$

To meet the design requirements five 1500µF, aluminum electrolytic capacitors are chosen for the design from United Chemi-Con™, part number EKY-160ELL152MJ30S. These capacitors have an ESR of 31mΩ.

The number of output capacitors (n) is 5.

The total output capacitance is calculated using 式 71:

$$C_{OUT} = 1500\,\mu F \times n \approx 7500\,\mu F \tag{71}$$

The effective output capacitance ESR is calculated using 式 72:

$$ESR_{COUT} = \frac{31m\Omega}{n} = 6.2\,m\Omega \tag{72}$$

Calculate output capacitor loss (P_{COUT}) using 式 73:

$$P_{COUT} = I_{COUT\_RMS}^{2} \times ESR_{COUT} \approx 0.21W \tag{73}$$

Recalculate the remaining Power Budget using 式 74:

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$$P_{BUDGET} = P_{BUDGET} - P_{COUT} \approx 25.2\,W \tag{74}$$

7.2.2.8 Select FETs QE and QF

Selecting FETs for a design is an iterative process. To meet the power requirements of this design, we select 75V, 120A FETs, from Fairchild, part number FDP032N08. These FETs have the following characteristics.

$$QE_g = 152nC \tag{75}$$

$$R_{ds(on)QE} = 3.2m\Omega \tag{76}$$

Calculate average FET C_{OSS} ($C_{OSS\_QE\_AVG}$) based on the data sheet parameters for C_{OSS} (C_{OSS_SPEC}), and drain to source voltage where C_{OSS_SPEC} was measured (V_{ds_spec}), and the maximum drain to source voltage in the design (V_{dsQE}) that will be applied to the FET in the application.

The voltage across FET QE and QF when they are of isf:

$$V_{dsQE} = \frac{2V_{INMAX}}{a1} = 39\,V \tag{77}$$

The voltage where FET C_{OSS} is specified and tested in the FET data sheet:

$$V_{ds\_spec} = 25\,V \tag{78}$$

The specified output capacitance from FET data sheet is:

$$C_{OSS\_SPEC} = 1810\,pF \tag{79}$$

The average QE and QF C_{OSS} [2] is calculated using 式 80:

$$C_{OSS\_QE\_AVG} = C_{OSS\_SPEC}\sqrt{\frac{V_{ds\_SPEC}}{V_{dsQE}}} \approx 1.9nF \tag{80}$$

The QE and QF RMS current are:

$$I_{QE\_RMS} = I_{SRMS} = 36.0\,A \tag{81}$$

To estimate FET switching loss the V_g vs. Q_g curve from the FET data sheet needs to be studied. First the gate charge at the beginning of the miller plateau needs to be determined (QE_{MILLER_MIN}) and the gate charge at the end of the miller plateau (QE_{MILLER_MAX}) for the given V_{DS}.

The maximum gate charge at the end of the miller plateau is:

$$QE_{MILLER\_MAX} \approx 100nC \tag{82}$$

The minimum gate charge at the beginning of the miller plateau is:

$$QE_{MILLER\_MIN} \approx 52nC \tag{83}$$

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注

The FETs in this design are driven with a UCC27324 Gate Driver IC, setup to drive 4A (I_P) of gate drive current.

$$I_P \approx 4\,A \tag{84}$$

Estimated FET V_{ds} rise and fall time using 式 85:

$$t_r \approx t_f = \frac{100nC - 52nC}{\frac{I_P}{2}} = \frac{48nC}{\frac{4A}{2}} \approx 24\,ns \tag{85}$$

Estimate QE and QF FET Losses (P_{QE}) using 式 86:

$$P_{QE} = I_{QE\_RMS}{}^2 \times R_{ds(on)QE} + \frac{P_{OUT}}{V_{OUT}} \times V_{dsQE}\left(t_r + t_f\right) f_{SW} + 2 \times C_{OSS\_QE\_AVG} \times V_{dsQE}{}^2 f_{SW} + 2 \times Q_{gQE} \times V_{gQE} f_{SW} \tag{86}$$

$$P_{QE} \approx 9.3\,W \tag{87}$$

Recalculate the power budget using 式 88.

$$P_{BUDGET} = P_{BUDGET} - 2 \times P_{QE} \approx 6.5\,W \tag{88}$$

7.2.2.9 Input Capacitance (C_{IN})

The input voltage in this design is $390V_{DC}$, which is typically fed by the output of a PFC boost pre-regulator. It is typical to select input capacitance based on holdup and ripple requirements.

注

The delay time needed to achieve ZVS can act as a duty cycle clamp (D_{CLAMP}).

Calculate tank frequency using 式 89:

$$f_R = \frac{1}{2\pi\sqrt{L_S \times (2 \times C_{OSS\_QA\_AVG})}} \tag{89}$$

Estimate the delay time using 式 90:

$$t_{DELAY} = \frac{2}{f_R \times 4} \approx 314\,ns \tag{90}$$

The effective duty cycle clamp (D_{CLAMP}) is calculated in 式 91:

$$D_{CLAMP} = \left(\frac{1}{2 \times f_{SW}} - t_{DELAY}\right) \times 2 \times f_{SW} = 94\% \tag{91}$$

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V_{DROP} is the minimum input voltage where the converter can still maintain output regulation (see 式 92). The converter's input voltage would only drop down this low during a brownout or line-drop condition if this converter was following a PFC pre-regulator.

$$V_{DROP} = \left(\frac{2 \times D_{CLAMP} \times V_{RDSON} + a1 \times (V_{OUT} + V_{RDSON})}{D_{CLAMP}} \right) = 276.2\,V \tag{92}$$

C_{IN} was calculated in 式 93 based on one line cycle of holdup:

$$C_{IN} \geq \frac{2 \times P_{OUT} \times \frac{1}{60\,Hz}}{\left(V_{IN}^{\ 2} - V_{DROP}^{\ 2} \right)} \approx 364\,\mu F \tag{93}$$

Calculate the high-frequency input capacitor RMS current (I_{CINRMS}) using 式 94.

$$I_{CINRMS} = \sqrt{I_{PRMS1}^{\ 2} - \left(\frac{P_{OUT}}{V_{VIN(min)} \times \eta} \right)} = 1.8\,A \tag{94}$$

To meet the input capacitance and RMS current requirements for this design, a 330µF capacitor was chosen from Panasonic part number EETHC2W331EA:

C_{IN} = 330µF

This capacitor has a high frequency (ESR_{CIN}) of 150mΩ and is measured with an impedance analyzer at 200kHz. ESR_{CIN} = 0.150Ω

Estimate the C_{IN} power dissipation (P_{CIN}) using 式 95:

$$P_{CIN} = I_{CINRMS}^{\ 2} \times ESR_{CIN} = 0.5\,W \tag{95}$$

And recalculate the remaining power budget using 式 96:

$$P_{BUDGET} = P_{BUDGET} - P_{CIN} \approx 6.0\,W \tag{96}$$

There is approximately 6.0W that remains in the power budget for the current-sensing network, to bias the control device, and for all resistors supporting the control device.

7.2.2.10 Current Sense Network (CT, R_{CS}, R7, D_A)

The CT chosen for this design has a turns ratio (CT_{RAT}) of 100:1 in 式 97:

$$CT_{RAT} = \frac{I_P}{I_S} = 100 \tag{97}$$

Calculate nominal peak current (I_{P1}) at V_{INMIN}:

The peak primary current is calculated using 式 98:

$$I_{P1} = \left(\frac{P_{OUT}}{V_{OUT} \times \eta} + \frac{\Delta I_{LOUT}}{2} \right) \frac{1}{a1} + \frac{V_{INMIN} \times D_{MAX}}{L_{MAG} \times 2 \times F_{SW}} \approx 3.3\,A \tag{98}$$

The CS pin voltage where peak current limit will trip is:

$$V_P = 2\,V \tag{99}$$

Calculate current sense resistor (R_{CS}) and leave 300mV for slope compensation using 式 100. Include a 1.1 factor for margin:

$$R_{CS} = \frac{V_P - 0.3\,V}{\frac{I_{P1}}{CT_{RAT}} \times 1.1} \approx 47\,\Omega \tag{100}$$

Select a standard resistor for R_{CS}:

$$R_{CS} = 47\,\Omega \tag{101}$$

Estimate the power loss for R_{CS} using 式 102:

$$P_{RCS} = \left(\frac{I_{PRMS1}}{CT_{RAT}}\right)^2 \times R_{CS} \approx 0.03\,W \tag{102}$$

Calculate maximum reverse voltage (V_{DA}) on D_A using 式 103:

$$V_{DA} = V_P \frac{D_{CLAMP}}{1 - D_{CLAMP}} \approx 29.8\,V \tag{103}$$

Estimate the D_A power loss (P_{DA}) using 式 104:

$$P_{DA} = \frac{P_{OUT} \times 0.6\,V}{V_{INMIN} \times \eta \times CT_{RAT}} \approx 0.01W \tag{104}$$

Calculate reset resistor R7:

Resistor R7 is used to reset the current sense transformer CT:

$$R7 = 100 \times R_{CS} = 4.7\,k\Omega \tag{105}$$

Resistor R_{LF1} and capacitor C_{LF} form a low-pass filter for the current sense signal (Pin 15). For this design, chose the following values. This filter has a low frequency pole (f_{LFP}) at 482kHz, (which is appropriate for most applications) but may be adjusted to suit individual layouts and EMI present in the design.

$$R_{LF1} = 1k\Omega \tag{106}$$

$$C_{LF} = 330\,pF \tag{107}$$

$$f_{LFP} = \frac{1}{2\pi f \times R_{LF1} \times C_{LF}} = 482\,kHz \tag{108}$$

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The UCC2895x VREF output (Pin 1) needs a high frequency bypass capacitor to filter out high frequency noise. This pin needs at least 1µF of high-frequency bypass capacitance (C_{REF}).

$$C_{REF} = 1\,\mu F \tag{109}$$

The voltage amplifier reference voltage (Pin 2, EA +) can be set with a voltage divider (R1, R2), for this design example, the error amplifier reference voltage (V1) will be set to 2.5V. Select a standard resistor value for R1 and then calculate resistor value R2.

UCC2895x reference voltage:

$$V_{REF} = 5\,V \tag{110}$$

Set voltage amplifier reference voltage:

$$V1 = 2.5\,V \tag{111}$$

$$R1 = 2.37\,k\Omega \tag{112}$$

$$R2 = \frac{R1 \times (V_{REF} - V1)}{V1} = 2.37\,k\Omega \tag{113}$$

The voltage divider formed by resistor R3 and R4 are chosen to set the DC output voltage (V_{OUT}) at Pin 3 (EA-).

Select a standard resistor for R3:

$$R3 = 2.37\,k\Omega \tag{114}$$

Calculate R4 using 式 115:

$$R4 = \frac{R3 \times (V_{OUT} - V1)}{V1} \approx 9\,k\Omega \tag{115}$$

Then choose a standard resistor for R4 using 式 116:

$$R4 = \frac{R3 \times (V_{OUT} - V1)}{V1} \approx 9.09\,k\Omega \tag{116}$$

注

TI recommends using an RCD clamp to protect the output synchronous FETs from overvoltage due to switch node ringing.

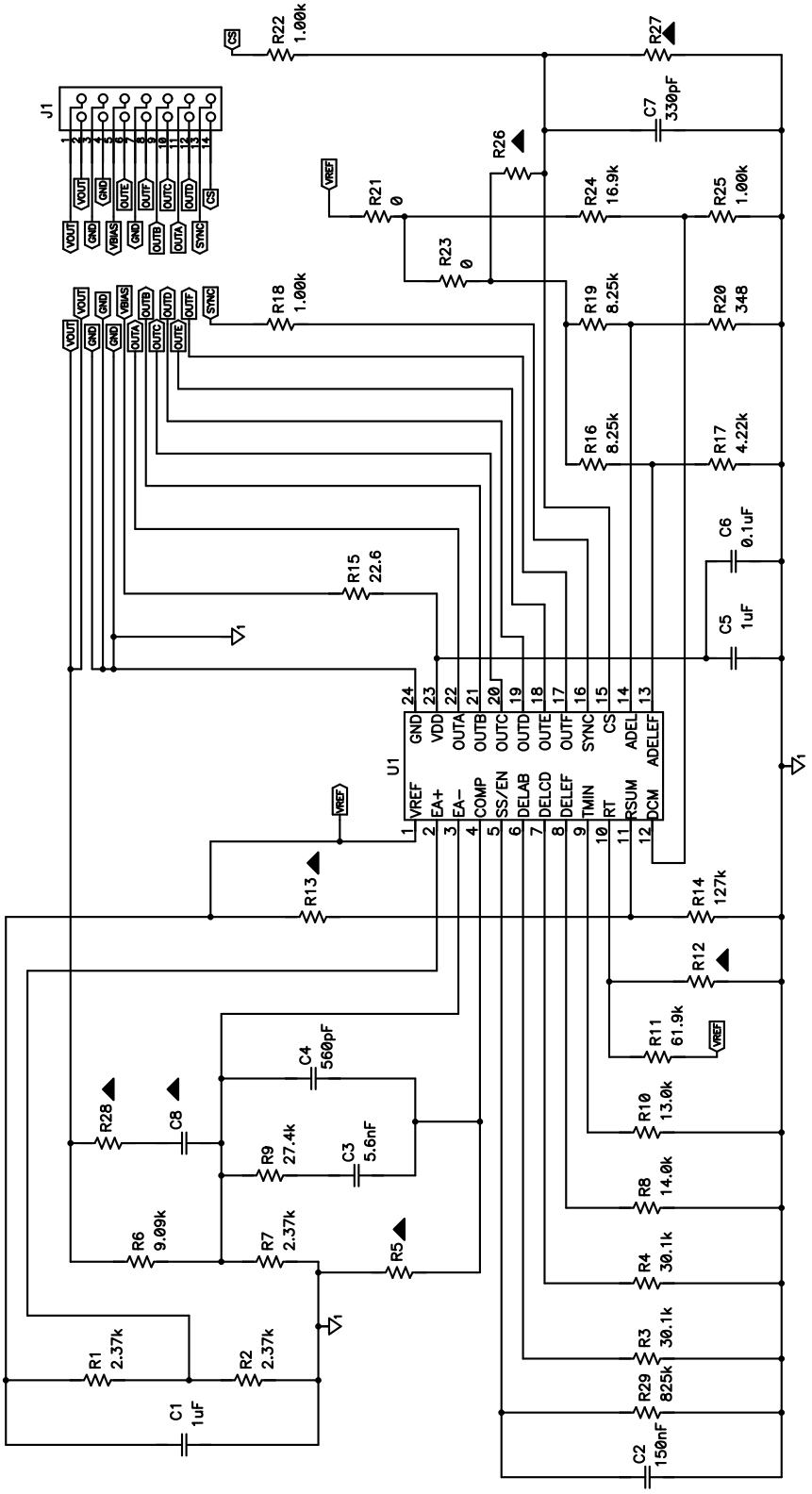

図 7-5. Daughter Board Schematic

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7.2.2.10.1 Voltage Loop Compensation Recommendation

For best results in the voltage loop, TI recommends using a Type 2 or Type 3 compensation network (図 7-6). A Type 2 compensation network does not require passive components C_{Z2} and R_{Z2}. Type 1 compensation is not versatile enough for a phase-shifted full bridge. When evaluating the COMP pin for best results, TI recommends placing a 1-kΩ resistor between the scope probe and the COMP pin of the UCC2895x.

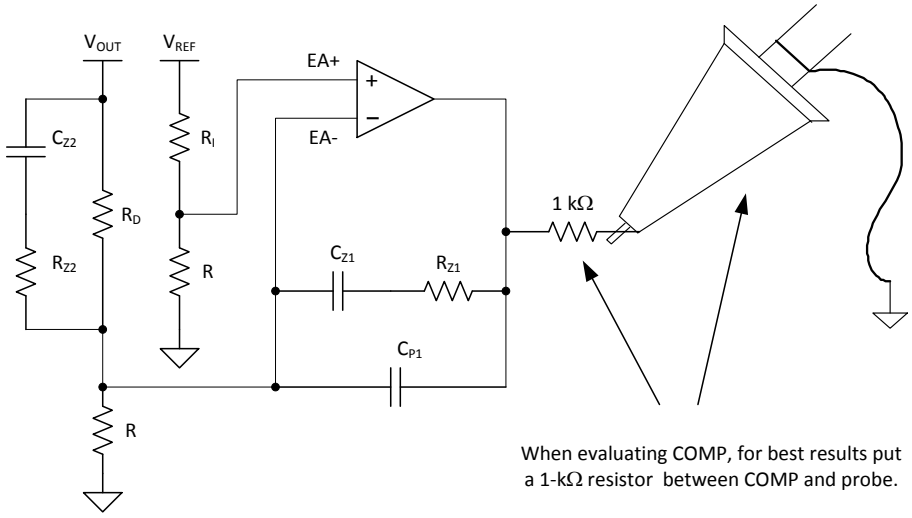

図 7-6. Type 3 Compensation Evaluation

Compensating the feedback loop can be accomplished by properly selecting the feedback components (R5, C1 and C2). These components are placed as close as possible to pin 3 and 4 of the controller. A Type 2 compensation network is designed in this example.

Calculate load impedance at 10% load (R_{LOAD}) :

$$R_{LOAD} = \frac{V_{OUT}^{2}}{P_{OUT} \times 0.1} = 2.4\,\Omega \tag{117}$$

Approximate control to output transfer function ($G_{CO}(f)$) as a function of frequency:

$$G_{CO}(f) \approx \frac{\Delta V_{OUT}}{\Delta V_C} = a1 \times CT_{RAT} \times \frac{R_{LOAD}}{R_{CS}} \times \left(\frac{1 + 2\pi j \times f \times ESR_{COUT} \times C_{OUT}}{1 + 2\pi j \times f \times R_{LOAD} \times C_{OUT}} \right) \times \frac{1}{1 + \frac{S(f)}{2\pi \times f_{PP}} + \left(\frac{S(f)}{2\pi \times f_{PP}} \right)^{2}} \tag{118}$$

Calculate double pole frequency of $G_{CO}(f)$:

$$f_{PP} \approx \frac{F_{SW}}{2} = 50\,kHz \tag{119}$$

Calculate angular velocity:

$$S(f) = 2\pi \times j \times f \tag{120}$$

Compensate the voltage loop with Type 2 feedback network. The following transfer function is the compensation gain as a function of frequency ($G_C(f)$):

$$G_C(f) = \frac{\Delta V_C}{\Delta V_{OUT}} = \frac{2\pi j \times f \times R5 \times C2 + 1}{2\pi j \times f \times (C2 + C1) R4 \left(\frac{2\pi j \times f \times C2 \times C1 \times R5}{C2 + C1} + 1 \right)} \tag{121}$$

Calculate voltage loop feedback resistor (R5) based on the crossing the voltage loop (f_C) over at a 10th of the double pole frequency (f_{PP}):

$$f_C = \frac{f_{PP}}{10} = 5\,kHz \tag{122}$$

$$R5 = \frac{R4}{G_{CO}\left(\frac{f_{PP}}{10}\right)} \approx 27.9\,k\Omega \tag{123}$$

The standard resistor selcted for R5 is 27.4 kΩ.

Calculate the feedback capacitor (C2) to give added phase at crossover:

$$C2 = \frac{1}{2 \times \pi \times R5 \times \frac{f_C}{5}} \approx 5.8\,nF \tag{124}$$

The standard capacitance value (C2) selected for the design is 5.6 nF.

Put a pole at two times f_C:

$$C1 = \frac{1}{2 \times \pi \times R5 \times f_C \times 2} \approx 580\,pF \tag{125}$$

The standard capacitance value (C1) selected for the design is 560 pF.

Use 式 126 to calculate the loop gain as a function of frequency ($T_V(f)$) in dB.

$$T_V dB(f) = 20 \log\left(\left|G_C(f) \times G_{CO}(f)\right|\right) \tag{126}$$

Plot a theoretical loop gain and phase to graphically confirm loop stability. The theoretical loop gain crosses over at roughly 3.7 kHz with a phase margin of greater than 90 degrees.

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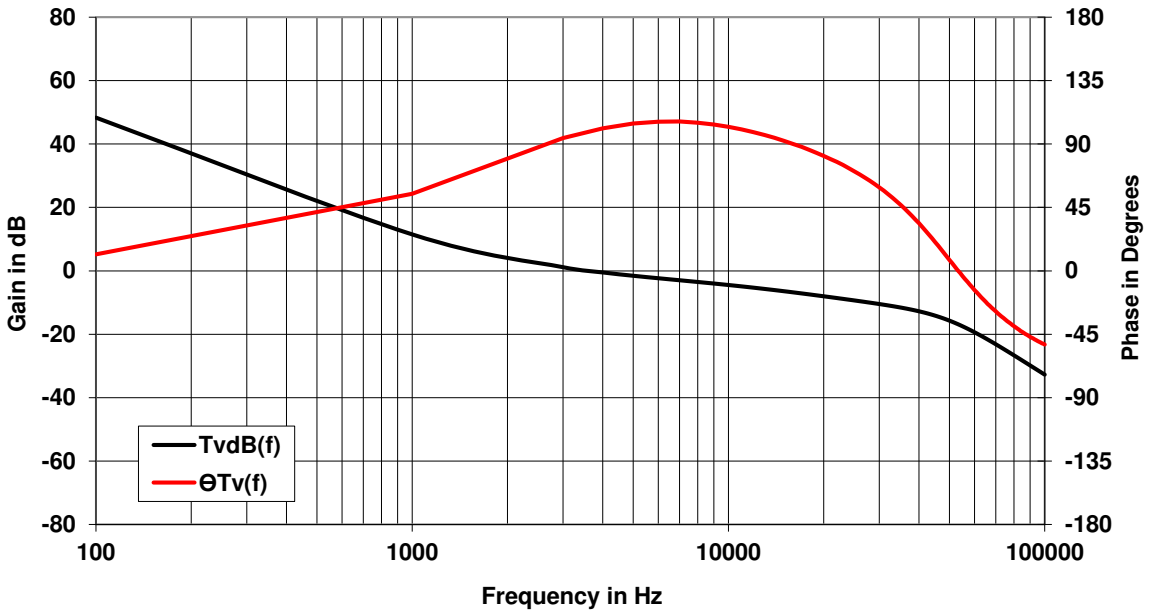

図 7-7. Loop Gain and Phase vs Frequency

注

TI recommends confirming the loop stability of the final design with transient testing and/or a network analyzer. Adjust the compensation ($G_C(f)$) feedback as necessary.

$$L_{MAG} \geq \frac{V_{IN} \times (1 - D_{TYP})}{\frac{\Delta I_{LOUT} \times 0.5}{a1} \times 2 \times F_{SW}} \approx 2.78\,mH \quad (127)$$

where

- loop gain ($T_V dB(f)$)
- loop phase ($\Phi T_V(f)$)

To limit overshoot during the power up sequence, the UCC2895x has a soft-start function (SS, Pin 5). In this application the soft-start time is 15 ms (t_{SS}).

$$C_{SS} = \frac{t_{SS} \times 25\,\mu A}{V1 + 0.55} \approx 123\,nF \quad (128)$$

The standard capacitor (C_{SS}) selected for this design is 150 nF.

This application presents a fixed delay approach to achieving ZVS from 100% load down to 50% load. Adaptive delays can be generated by connecting the ADEL and ADELEF pins to the CS pin as shown in 図 7-8 .

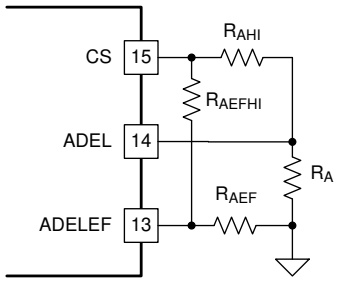

図 7-8. Adaptive Delays

When the converter is operating below 50% load, the converter operates in valley switching. To achieve zero voltage switching on switch node of QB_d, the turn-on (t_{ABSET}) delays of FETs QA and QB must be initially set based on the interaction of L_S and the theoretical switch node capacitance. The following equations are used to set t_{ABSET} initially.

Equate shim inductance to two times C_{OSS} capacitance using 式 129:

$$2\pi \times f_R L_S = \frac{1}{2\pi \times f_R \times (2 \times C_{OSS\_QA\_AVG})} \tag{129}$$

Calculate tank frequency using 式 130:

$$f_R = \frac{1}{2\pi \sqrt{L_S \times (2 \times C_{OSS\_QA\_AVG})}} \tag{130}$$

Set initial t_{ABSET} delay time and adjust as necessary.

注

The 2.25 factor of the t_{ABSET} equation was derived from empirical test data and may vary based on individual design differences.

$$t_{ABSET} = \frac{2.25}{f_R \times 4} \approx 346\,\text{ns} \tag{131}$$

The resistor divider formed by R_A and R_{AHI} programs the t_{ABSET}, t_{CDSET} delay range of the controller. The standard resistor value R_{AHI} selected is 8.25 kΩ.

t_{ABSET} can be programmed between 30 ns to 1000 ns.

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The voltage at the ADEL input of the controller (V_{ADEL}) must be set with R_A based on the following conditions:

- If t_{ABSET} > 155 ns, set V_{ADEL} = 0.2 V. t_{ABSET} can be programmed between 155 ns and 1000 ns.
- If t_{ABSET} ≤ 155 ns, set V_{ADEL} = 1.8 V. t_{ABSET} can be programmed between 29 ns and 155 ns.

Based on V_{ADEL} selection, calculate R_A:

$$R_A = \frac{R_{AHI} \times V_{ADEL}}{5V - V_{ADEL}} \approx 344\,\Omega \tag{132}$$

The closest standard resistor value for R_A selected is 348 Ω.

Recalculate V_{ADEL} based on resistor divider selection:

$$V_{ADEL} = \frac{5\,V \times R_A}{R_{AHI} + R_A} = 0.202\,V \tag{133}$$

Resistor R_{AB} programs t_{ABSET}. Variable CS is the voltage at the CS pin with respect to ground and ratio K_A was calculated in 式 5:

$$R_{AB} = \frac{T_{ABSET}}{5} \times \left(0.26 + CS \times K_A \times 1.3\right) \approx 30.6k\Omega \tag{134}$$

The standard resistor value for R_{AB} selected for the design is 30.1 kΩ.

注

After a prototype oprational, fine tune t_{ABSET} during light-load operation to the peak and valley of the resonance between L_S and the switch node capacitance. In this design, the delay was set at 10% load.

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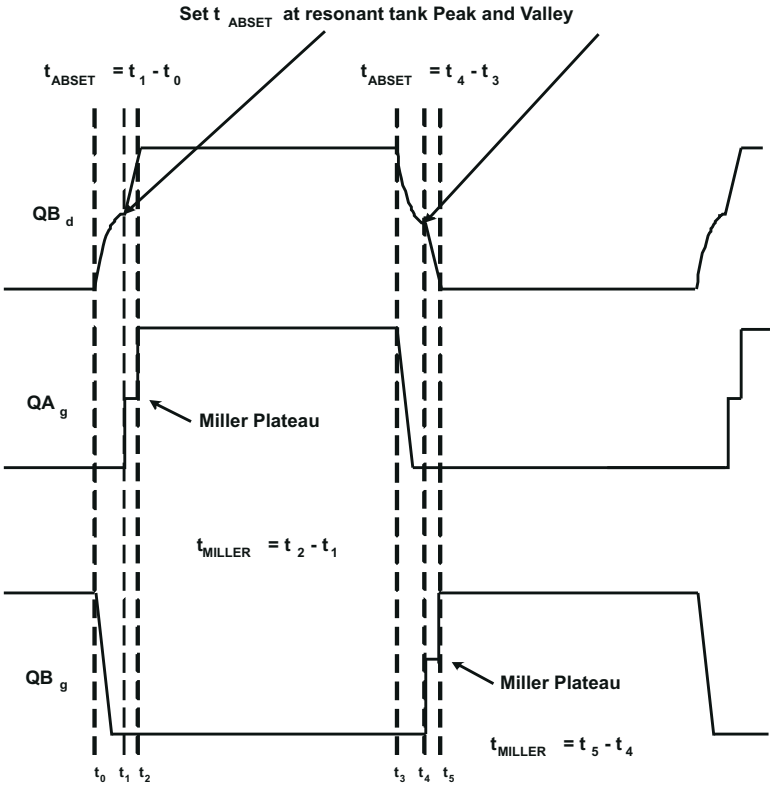

図 7-9. t_{ABSET} to Achieve Valley Switching at Light Loads

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Initially, set the QC and QD turn-on delays (t_{CDSET}) for the same delay as the QA and QB turn-on delays (Pin 6). The following equations program the QC and QD turn-on delays (t_{CDSET}) by properly selecting resistor R_{DELCD} (Pin 7).

$$t_{ABSET} = t_{CDSET} \tag{135}$$

Resistor R_{CD} programs t_{CDSET}:

$$R_{CD} = \frac{T_{CDSET}}{5} \times \left(0.26 + CS \times K_A \times 1.3\right) \approx 30.6k\Omega \tag{136}$$

The standard resistor R_{CD} selected for this design is 30.1 kΩ.

注

After a prototype operational, fine tune t_{CDSET} during light-load operation. In this design, the CD node was set to valley switch at roughly 10% load.. Obtaining ZVS at lighter loads with switch node QD_d is easier due to the reflected output current present in the primary of the transformer at FET QD and QC during the turnoff or turnon period. This behavior is due to more peak current available to energize L_S before this transition, compared to the QA and QB turnoff and turnon period.

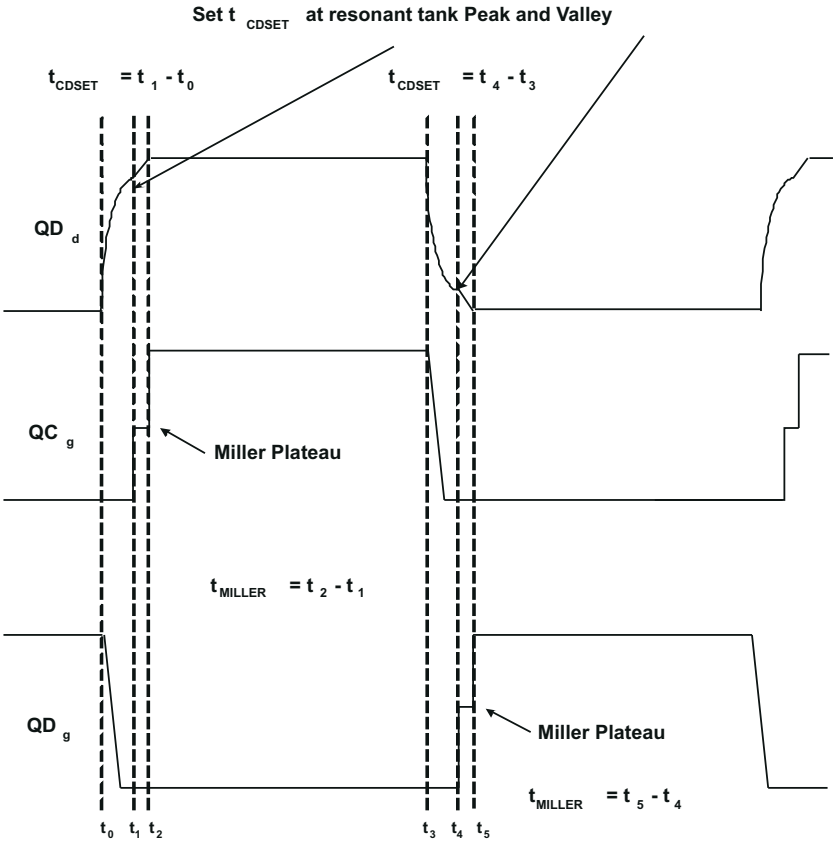

図 7-10. t_{CDSET} to Achieve Valley Switching at Light Loads

There is a programmable delay for the turnoff of FET QF after FET QA turnoff (t_{AFSET}) and the turnoff of FET QE after FET QB turnoff (t_{BESET}). Set these delays to 50% of t_{ABSET} to ensure that the appropriate synchronous rectifier turns off before the AB ZVS transition. If this delay is too large, it causes OUTE and OUTF not to overlap correctly and creates excess body diode conduction on FETs QE and QF.

$$t_{AFSET} = t_{BESET} = t_{ABSET} \times 0.5 \tag{137}$$

The resistor divider formed by R_{AEF} and R_{AEFHI} programs the t_{AFSET} and t_{BESET} delay range of the controller. The standard resistor value selected for R_{AEFHI} is 8.25 kΩ.

注

t_{AFSET} and t_{BESET} can be programmed between 32 ns to 1100 ns.

The voltage at the ADELEF pin of the controller (V_{ADELEF}) needs to be set with R_{AEF} based on the following conditions.

- If t_{AFSET} < 170 ns set V_{ADEL} = 0.2 V, t_{ABSET} can be programmed between 32 ns and 170 ns.
- If t_{ABSET} > or = 170 ns set V_{ADEL} = 1.7 V, t_{ABSET} can be programmed between 170 ns and 1100 ns.

Based on V_{ADELEF} selection, calculate R_{AEF}:

$$R_{AEF} = \frac{R_{AEFHI} \times V_{ADELEF}}{5\,V - V_{ADELEF}} \approx 4.25\,k\Omega \tag{138}$$

The closest standard resistor value for R_{AEF} is 4.22 kΩ.

Recalculate V_{ADELEF} based on resistor divider selection:

$$V_{ADELEF} = \frac{5\,V \times R_{AEF}}{R_{AEFHI} + R_{AEF}} = 1.692\,V \tag{139}$$

The following equation was used to program t_{AFSET} and t_{BESET} by properly selecting resistor R_{EF}.

$$R_{EF} = \frac{\left(t_{AFSET} \times 0.5 - 4\,ns\right)}{ns} \times \frac{\left(2.65\,V - V_{ADELEF} \times 1.32\right) \times 10^3}{5} \times \frac{1}{1A} \approx 14.1k\Omega \tag{140}$$

The standard resistor value selected for R_{EF} is 14 kΩ.

Resistor R_{TMIN} programs the minimum on time (t_{MIN}) that the UCC2895x (Pin 9) can demand before entering burst mode. If the UCC2895x controller tries to demand a duty cycle on time of less than t_{MIN} the power supply goes into burst mode operation. For this design set the minimum on-time (t_{MIN}) to 75 ns.

Set the minimum on-time by selecting R_{TMIN} :

$$R_{TMIN} = \frac{t_{MIN}}{5.92} \approx 12.7\,k\Omega \tag{141}$$

The standard resistor value for R_{TMIN} is 13 kΩ.

A resistor from the RT pin to ground sets the converter switching frequency calculated in 式 142.

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$$R_T = \left(\frac{2.5 \times 10^6 \times \frac{\Omega\ \text{Hz}}{\text{V}}}{\frac{f_{SW}}{2}} - \frac{\Omega}{\text{V}} \right) \times (V_{REF} - 2.5\ \text{V}) = 60\ \text{k}\Omega \quad (142)$$

The standard resistor value selected for R_T is 61.9 kΩ.

The UCC2895x provides slope compensation. The amount of slope compensation is set by the resistor R_{SUM}. As suggested earlier, set the slope compensation ramp to be half the inductor current ramp downslope (inductor current ramp during the off time), reflected through the main transformer and current sensing networks as explained earlier in *セクション 6.3.11*.

Calculate required slope compensation ramp:

$$me = 0.5 \times \frac{V_{OUT} \times R_{CS}}{L_{OUT} \times a1 \times CT_{RAT}} = 0.5 \times \frac{12 \times 47}{2 \times 10^{-6} \times 21 \times 100} = 67 \frac{mV}{\mu s} \quad (143)$$

The magnetizing current of the power transformer provides part of the slope compensation ramp. The slope of this current is calculated using 式 144 where V_{INHU} is the minimum voltage for V_{OUT} holdup purposes. It is the voltage at which the converter is operating at the maximum dudy cycle (D_{MAX}) while maintaining V_{OUT}:

$$m_{MAG} = \frac{V_{INHU} \times R_{CS}}{L_{MAG} \times CT_{RAT}} = \frac{260 \times 47}{2.76 x 10^{-3} \times 100} \approx 44 \frac{mV}{\mu s} \quad (144)$$

Calculate the required compensating ramp:

$$m_{SUM} = me - m_{MAG} = (67 - 44) \frac{mV}{\mu s} = 23 \frac{mV}{\mu s} \quad (145)$$

The value for the resistor, R_{SUM}, may be found from the graph in 図 6-10, calculated from rearranged versions of 式 13, or calculated by 式 13, depending on whether the controller is operating in current mode or voltage control mode. This design uses current mode control and 式 146 is rearranged and evaluated:

$$R_{SUM} = \frac{2.5}{0.5 \times m_{SUM}} = \frac{2.5}{0.5 \times 23 x 10^{-3}} \approx 200 k\Omega \quad (146)$$

Confirm that the 300 mV allowed for the slope compensation ramp is sufficient when choosing R_{CS} in 式 100.

$$\Delta V_{SLOPE-COMP} = \frac{m_{SUM} \times D_{MAX}}{2 \times F_{SW}} = \frac{23 \frac{mV}{\mu s} \times 0.7}{2 \times 100 kHz} = 80 mV \quad (147)$$

To increase efficiency at lighter loads the UCC2895x is programmed (Pin 12, DCM) under light-load conditions to disable the synchronous FETs on the secondary side of the converter (Q_E and Q_F). This threshold is programmed with resistor divider formed by R_{DCMHI} and R_{DCM}. This DCM threshold needs to be set at a level before the inductor current goes discontinuous. 式 148 sets the level at which the synchronous rectifiers are disabled at roughly 15% load current.

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$$V_{RCS} = \frac{\left(\frac{P_{OUT} \times 0.15}{V_{OUT}} + \frac{\Delta I_{LOUT}}{2}\right) \times R_{CS}}{a1 \times CT_{RAT}} = 0.29\,V \quad (148)$$

The standard resistor value selected for R_{DCM} is 1 kΩ.

Calculate resistor value R_{DCMHI}.

$$R_{DCMHI} = \frac{R_{DCM}\left(V_{REF} - V_{RCS}\right)}{V_{RCS}} \approx 16.3\,k\Omega \quad (149)$$

The standard resistor value for R_{DCMHI} is 16.9 kΩ.

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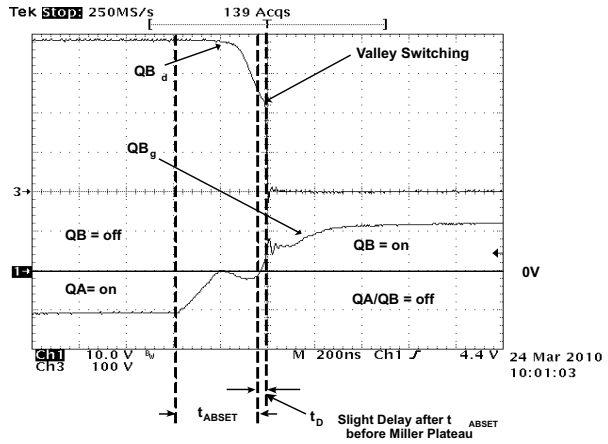
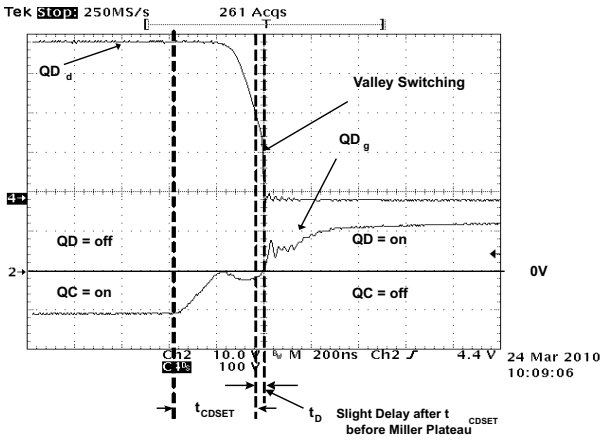
7.2.3 Application Curves

Switch node QBd is valley switching and node QDd has achieved ZVS. Please refer to 図 7-13 and 図 7-14. It is not uncommon for switch node QDd to obtain ZVS before QBd. This is because during the QDd switch node voltage transition, the reflected output current provides immediate energy for the LC tank at the switch node. Where at the QBd switch node transition the primary has been shorted out by the high-side or low-side FETs in the H bridge. This transition is dependent on the energy stored in LS and LLK to provide energy for the LC tank at switch node QBd making it take longer to achieve ZVS.



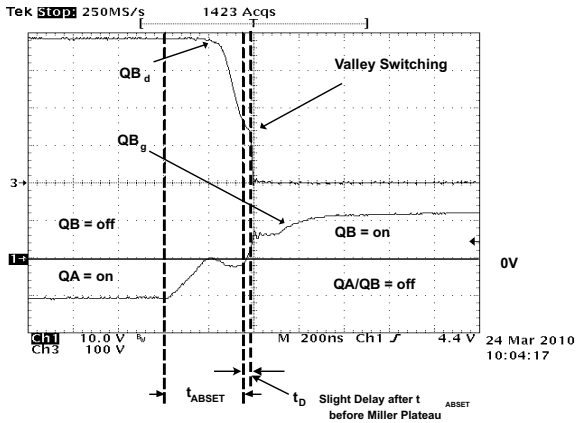
V_{IN} = 390V I_{OUT} = 5A

図 7-11. Full-Bridge Gate Drives and Primary Switch Nodes (QB_d and QD_d)



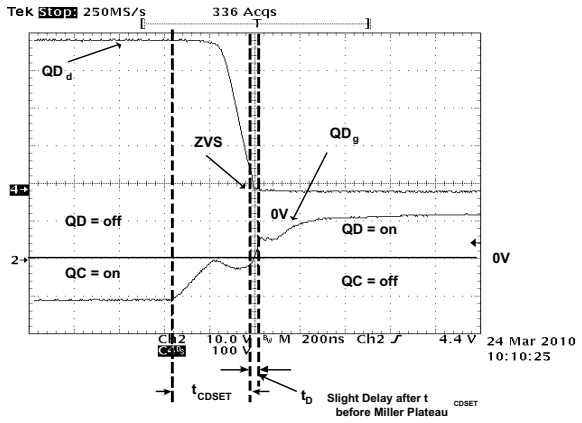
V_{IN} = 390V I_{OUT} = 5A

図 7-12. Full-Bridge Gate Drives and Primary Switch Nodes (QD_g QD_d)



V_{IN} = 390V I_{OUT} = 10A

図 7-13. Full-Bridge Gate Drives and Switch Nodes (QB_g QB_d)



V_{IN} = 390V I_{OUT} = 10A

図 7-14. Full-Bridge Gate Drives and Switch Nodes (QD_g QD_d)

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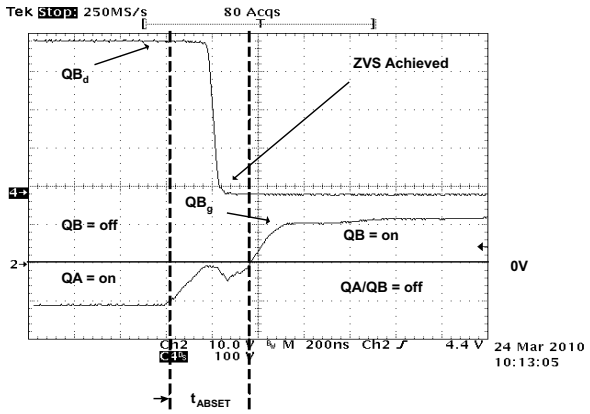
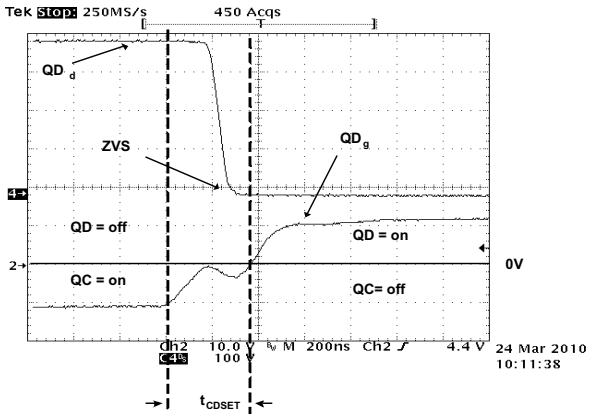


V_{IN} = 390V I_{OUT} = 25A

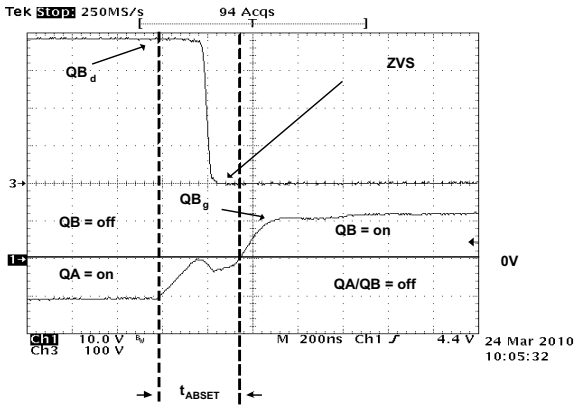
図 7-15. Full-Bridge Gate Drives and Switch Nodes (QB_g QB_d)



V_{IN} = 390V I_{OUT} = 25A

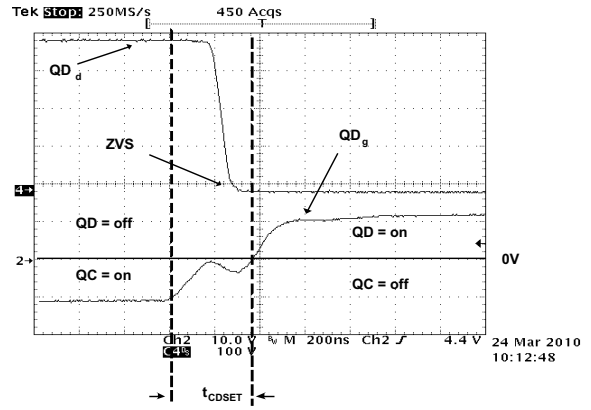
図 7-16. Full-Bridge Gate Drives and Switch Nodes (QD_g QD_d)

When the converter is running at 25A, both switch nodes are operating into zero voltage switching (ZVS). It is also worth mentioning that there is no evidence of the gate miller plateau during gate driver switching. This is because the voltage across the drains and sources of FETs QA through QD transitioned earlier.



V_{IN} = 390V I_{OUT} = 50A

図 7-17. Full-Bridge Gate Drives and Switch Nodes (QB_g QB_d)



V_{IN} = 390V I_{OUT} = 50A
ZVS maintained from 50% to 100% output power

図 7-18. Full-Bridge Gate Drives and Switch Nodes (QD_g QD_d)

7.3 Power Supply Recommendations

Operate the UCC2895x controller from a V_{DD} rail within the limits given in the *セクション 5.3* section of this data sheet. To avoid the possibility that the controller might stop switching, do not allow the V_{DD} to fall into the UVLO_FTH range. To minimize power dissipation in the controller, ensure that V_{DD} is not unnecessarily high. Maintaining V_{DD} at 12V is a good compromise between these competing constraints. The gate drive outputs from the controller deliver large-current pulses into their loads. This indicates the need for a low-ESR decoupling capacitor to be connected as directly as possible between the V_{DD} and GND terminals.

TI recommends ceramic capacitors with stable dielectric characteristics over temperature, such as X7R. Avoid capacitors which have a large drop in capacitance with applied DC voltage bias. For example, use a component that has a low-voltage co-efficient of capacitance. The recommended decoupling capacitance is 1µF, X7R, with at least a 25V rating with a 0.1µF NPO capacitor in parallel.

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7.4 Layout

7.4.1 Layout Guidelines

To increase the reliability and robustness of the design, TI recommends the following layout guidelines:

- For the VREF pin: decouple this pin to GND with a good quality ceramic capacitor. A 1µF, X7R, 25V capacitor is recommended. Keep VREF PCB tracks as far away as possible from sources of switching noise.
- For the EA+ pin: this is the noninverting input to the error amplifier. It is a high impedance pin and is susceptible to noise pickup. Keep tracks from this pin as short as possible.
- For theEA– pin: this is the inverting input to the error amplifier. It is a high impedance pin and is susceptible to noise pickup. Keep tracks from this pin as short as possible.
- For theCOMP pin: the error amplifier compensation network is normally connected to this pin. Keep tracks from this pin as short as possible.
- For theSS/EN pin: keep tracks from this pin as short as possible. If the Enable signal is coming from a remote source then avoid running it close to any source of high dv/dt (MOSFET Drain connections for example) and add a simple RC filter at the SS/EN pin.
- For the DELAB, DELCD, DELEF, TMIN, RT, R_{SUM}, DCM, ADELEF and ADEL pins: the components connected to these pins are used to set important operating parameters. Keep these components close to the IC and provide short, low impedance return connections to the GND pin.
- For the CS pin: this connection is arguably the most important single connection in the entire PSU system. Avoid running the CS signal traces near to sources of high dv/dt. Provide a simple RC filter as close to the pin as possible to help filter out leading edge noise spikes which occur at the beginning of each switching cycle.
- For the SYNC pin: this pin is essentially a digital I/O port. If it is unused, then it may be left open circuit or tied to ground through a 1kΩ resistor. If Synchronisation is used, then route the incoming Synchronisation signal as far away from noise sensitive input pins as possible.
- For the OUTA, OUTB, OUTC, OUTD, OUTE and OUTF pins: these are the gate drive output pins. They have a high dv/dt rate associated with their rising and falling edges. Keep the tracks from these pins as far away from noise sensitive input pins as possible. Ensure that the return currents from these outputs do not cause voltage changes in the analog ground connections to noise sensitive input pins. Follow the layout recommendation for analog and power ground planes in 図 6-18.
- For the VDD pin: this pin must be decoupled to GND using ceramic capacitors as detailed in the *セクション 7.3* section. Keep this capacitor as close to the VDD and GND pins as possible.
- For the GND pin: this pin provides the ground reference to the controller. Use a ground plane to minimize the impedance of the ground connection and to reduce noise pickup.

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7.4.2 Layout Example

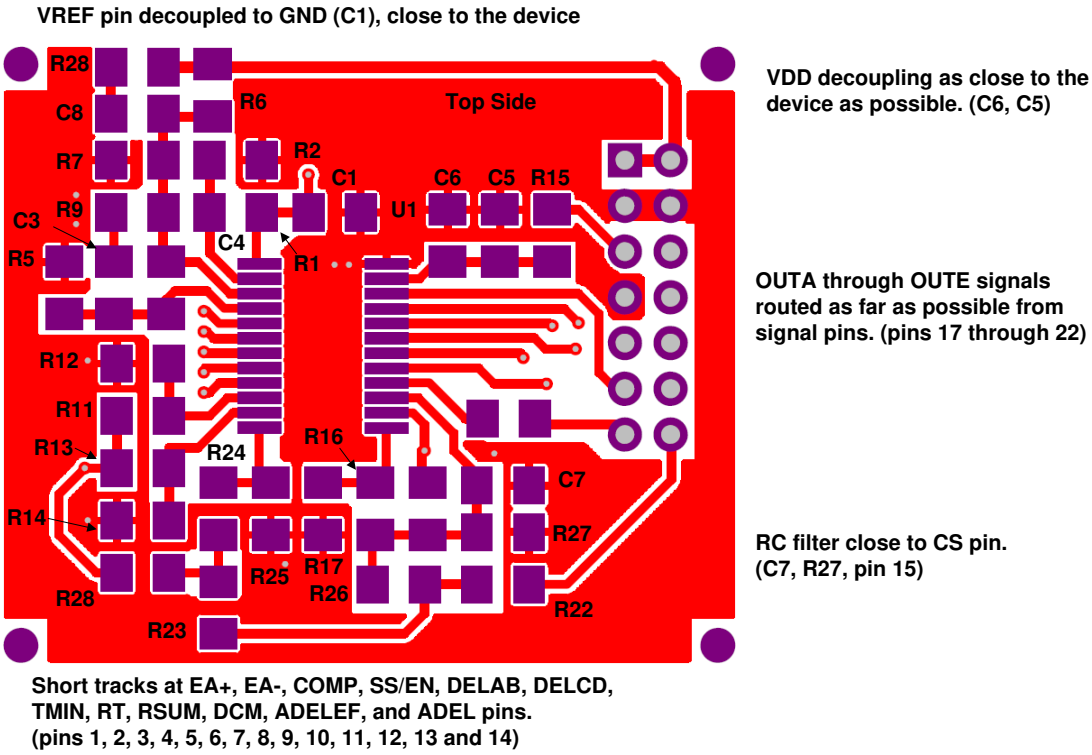

図 7-19. Layout Example (Top Side)

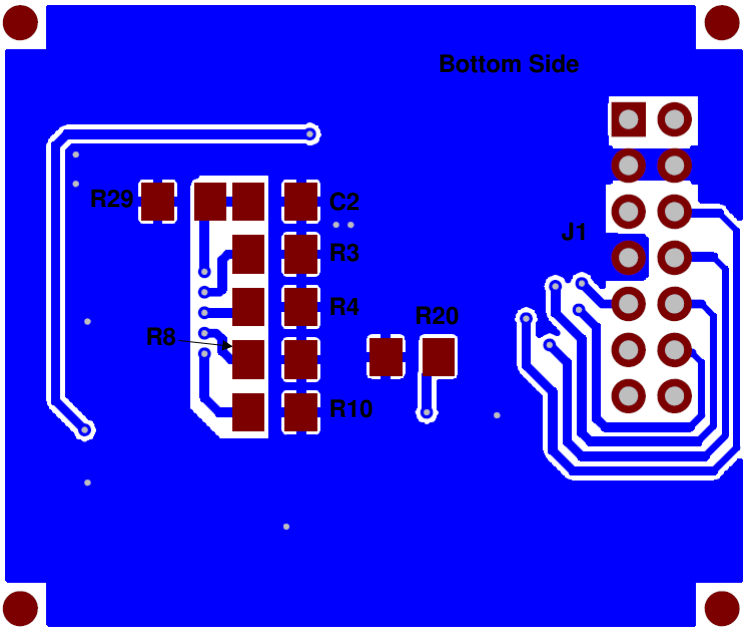

図 7-20. Layout Example (Bottom Side)

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8 Device and Documentation Support

8.1 Device Support

8.1.1 Development Support

UCC28950 MathCAD Design Tool.

UCC28950 Excel Design Tool.

8.2 Documentation Support

8.2.1 Related Documentation

For related documentation see the following:

- *Synchronizing Three or More UCC28950 Phase-Shifted, Full-Bridge Controllers* (SLUA609)
- *Making the Correct Choice: UCC28950-Q1 or UCC28951-Q1* (SLUA853)
- *Gate Drive Outputs on the UCC28950 and UCC28951-Q1 During Burst Mode Operation* (SLAU787)

8.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.4 Community Resources

8.5 Trademarks

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9 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision A (December 2021) to Revision B (October 2024)	Page
• UCC28951 のデータシートに UCC28950 デバイスを追加	1
• 「概要」セクションを変更	1
• Added D_{MAX} recommendations	5
• Updated T_{ABSET} and T_{CDSET} equations	21
• Updated T_{AFSET} and T_{BESET} equations	23
• Updated T_{AFSET} and T_{BESET} graphs	23
• Updated equations for $T_{CL(off\_leader)}$ and $T_{CL(off\_follower)}$ equations	31

Changes from Revision * (September 2018) to Revision A (December 2021)	Page
• 文書全体にわたって従来の用語をリーダーとフォロワに更新	1
• ドキュメント全体にわたって表、図、相互参照の採番方法を更新	1
• Changed note in *Soft-Start and Enable (SS/EN)* section	20
• Updated all equations in *Soft-Start and Enable (SS/EN)* section	20
• Updated m_o calculation equation	27
• Updated all equations in *Cycle-by-Cycle Current Limit Current Protection and Hiccup Mode* section	31
• Updated I_{CINRMS} calculation equation	52
• Updated resistor R_T calculation equation	57

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10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
UCC28950PW	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	UCC28950
UCC28950PW.A	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	UCC28950
UCC28950PWR	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	UCC28950
UCC28950PWR.A	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	UCC28950
UCC28950PWRG4	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	UCC28950
UCC28950PWRG4.A	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	UCC28950
UCC28951PWR	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCC28951
UCC28951PWR.A	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCC28951
UCC28951PWRG4	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCC28951
UCC28951PWRG4.A	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCC28951
UCC28951PWT	Active	Production	TSSOP (PW) | 24	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCC28951
UCC28951PWT.A	Active	Production	TSSOP (PW) | 24	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	UCC28951

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF UCC28950, UCC28951 :

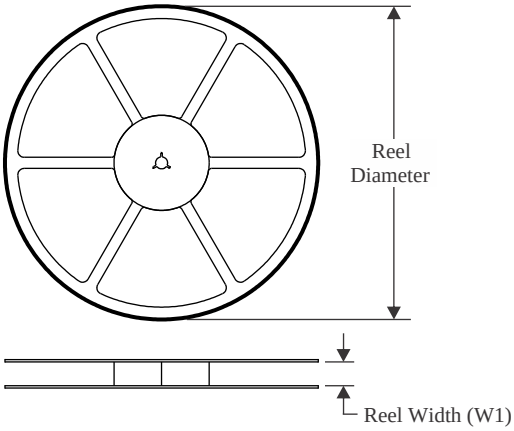
- Automotive : UCC28950-Q1, UCC28951-Q1

NOTE: Qualified Version Definitions:

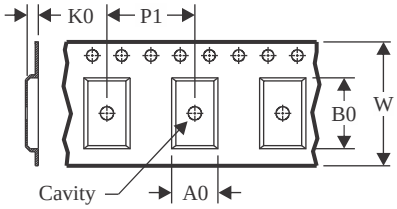
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

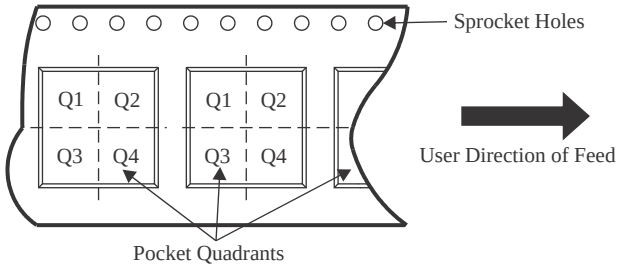


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

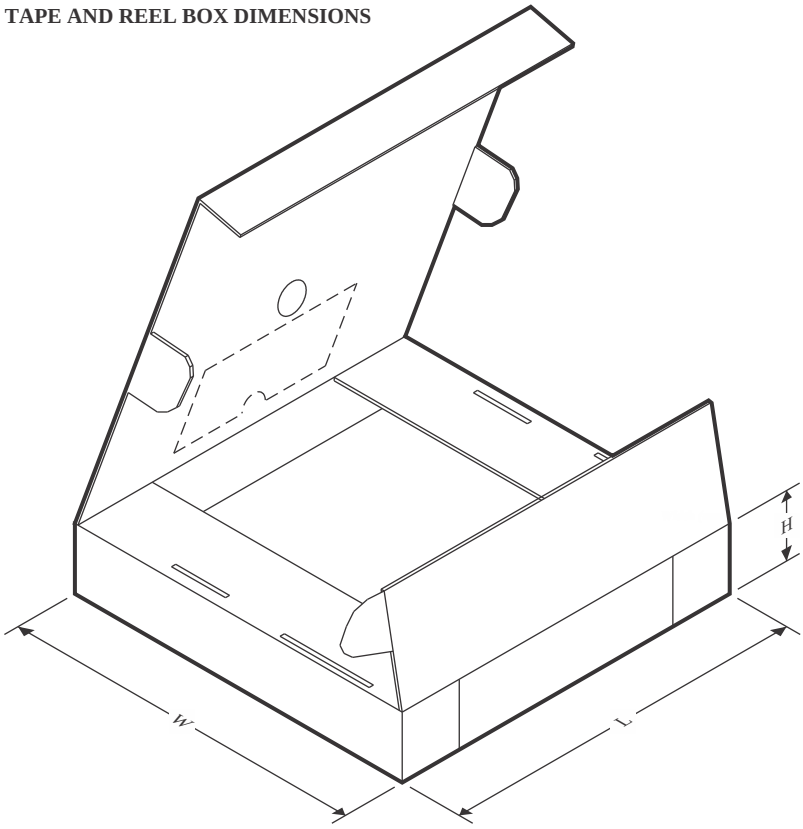
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC28950PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
UCC28950PWRG4	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
UCC28951PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
UCC28951PWRG4	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

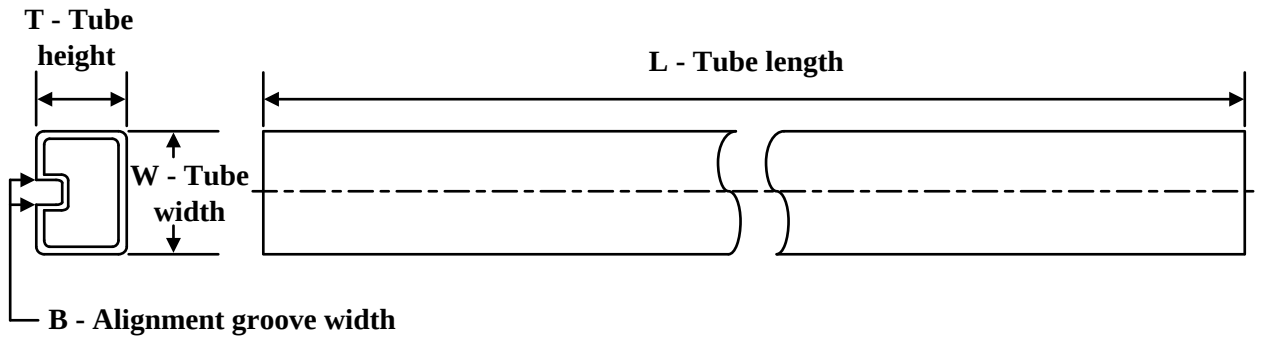
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC28950PWR	TSSOP	PW	24	2000	350.0	350.0	43.0
UCC28950PWRG4	TSSOP	PW	24	2000	350.0	350.0	43.0
UCC28951PWR	TSSOP	PW	24	2000	350.0	350.0	43.0
UCC28951PWRG4	TSSOP	PW	24	2000	350.0	350.0	43.0

TUBE



*All dimensions are nominal

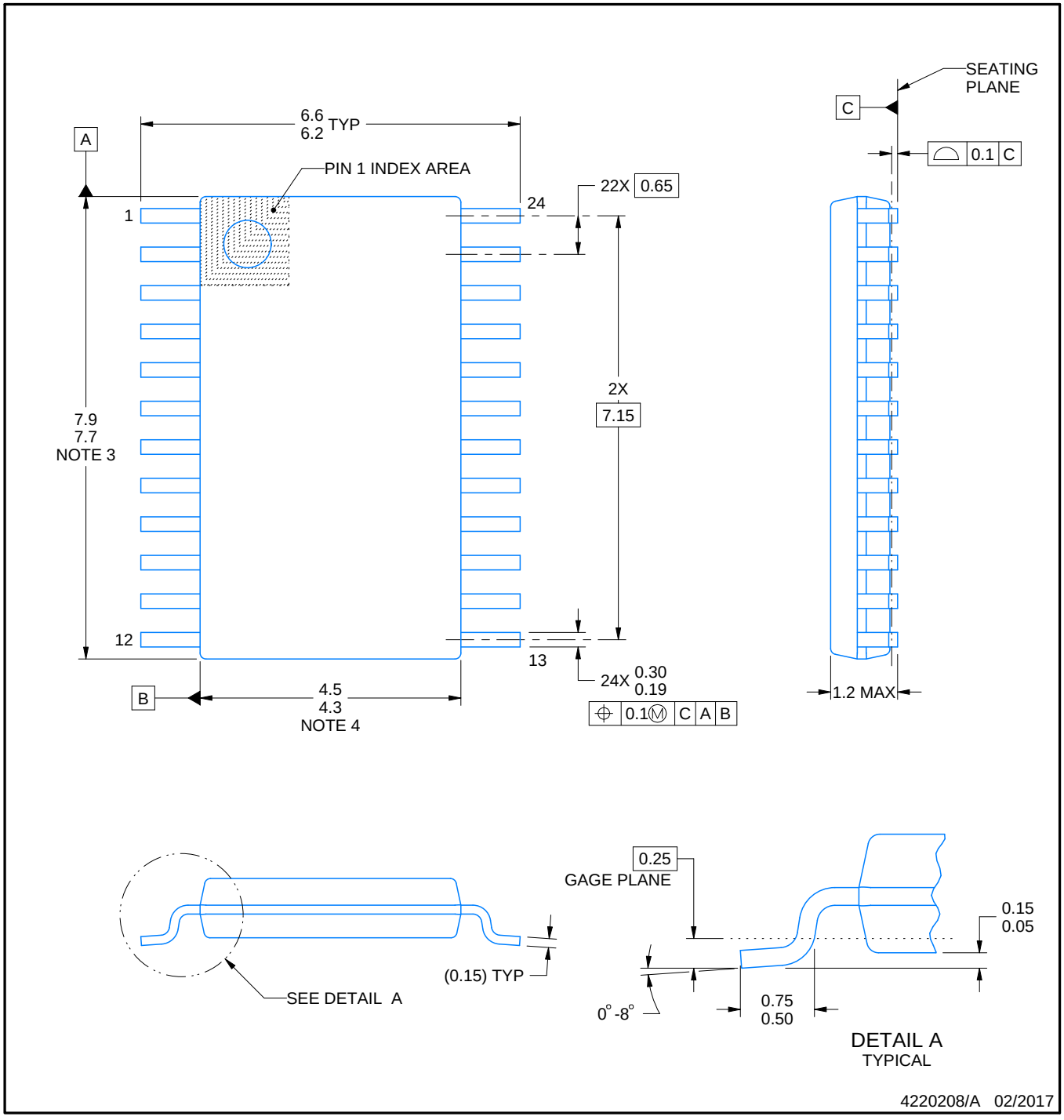
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
UCC28950PW	PW	TSSOP	24	60	530	10.2	3600	3.5
UCC28950PW.A	PW	TSSOP	24	60	530	10.2	3600	3.5

PACKAGE OUTLINE

PW0024A

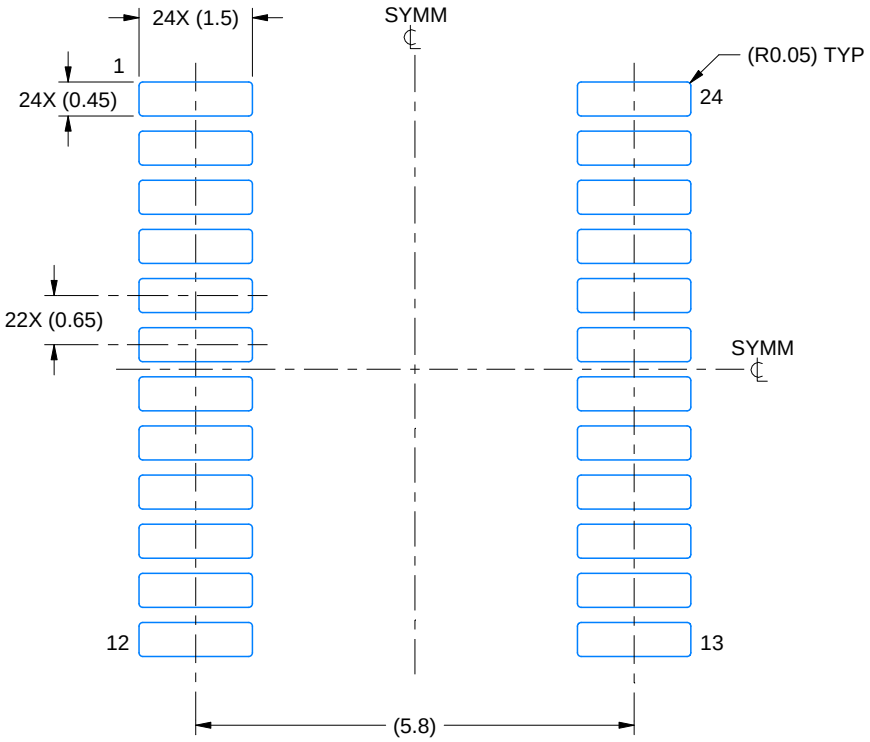
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

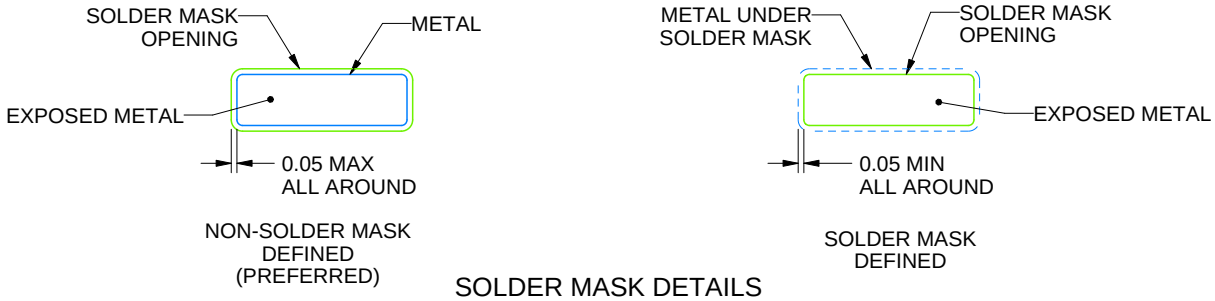


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

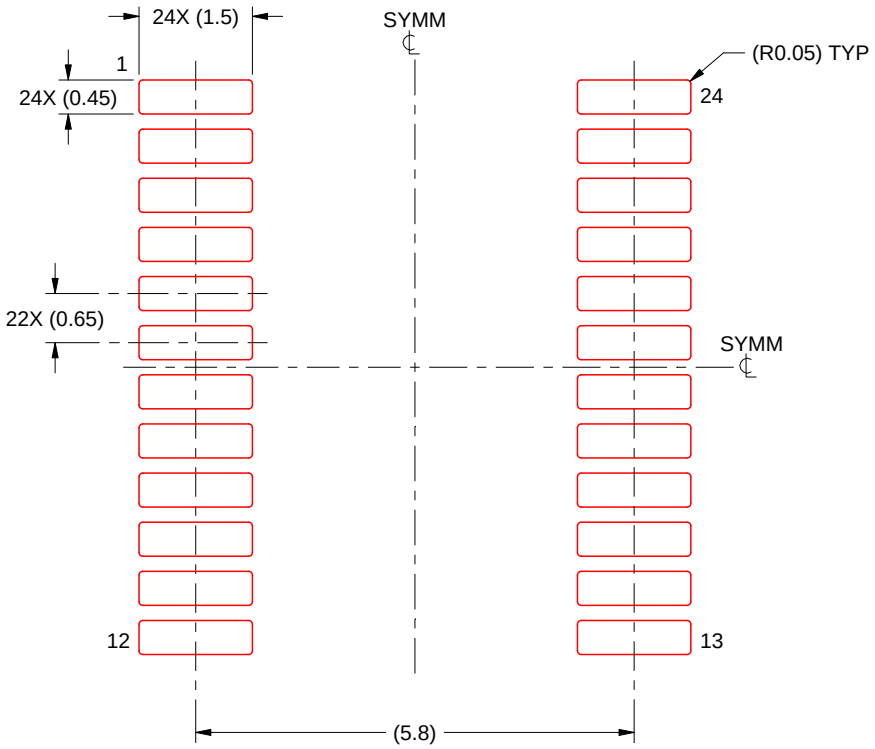


SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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最終更新日：2025 年 10 月